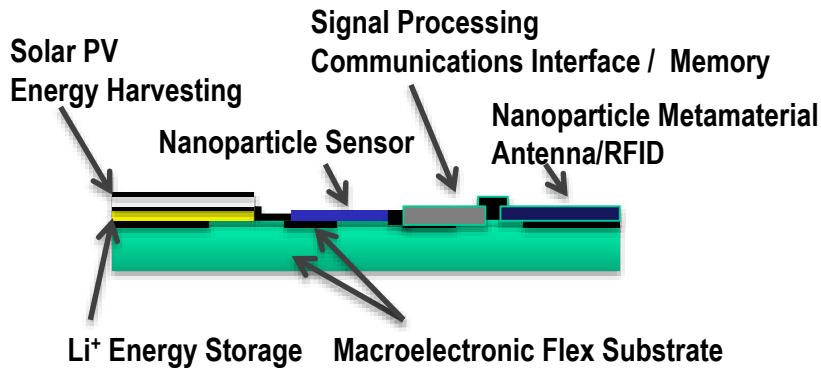


Functional Hybrid Materials using Additive-Driven Self Assembly and Nanoimprint Lithography: Towards Solution Based Nanomanufacturing



Jim Watkins

**Center for Hierarchical Manufacturing – NSF NSEC
Polymer Science and Engineering Department
University of Massachusetts, Amherst**

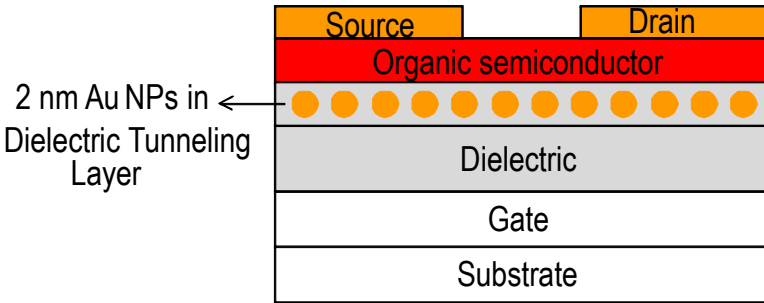


Today's Discussion

- **A Few Target Devices and Designs**
- **Scalability and Transitions to Roll-to-Roll**
- **Printing “Intelligent” Devices: Is it Possible?**
- **Imprint Lithography for Functional Nanostructures
(polymers/hybrids/crystalline metal oxides/metals)**
- **Additive Driven Self-Assembly for Functional Materials**
- **The Center for Personalized Health Monitoring and the New
Advanced Print and Roll-to-Roll Manufacturing Demo Facility at UMass**

Target Devices and Device Layers from Our Lab

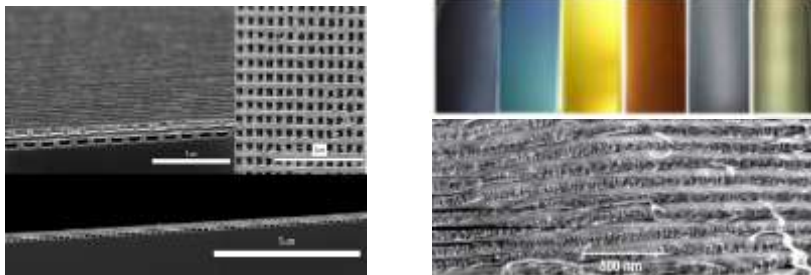
Printed Electronics / Memory



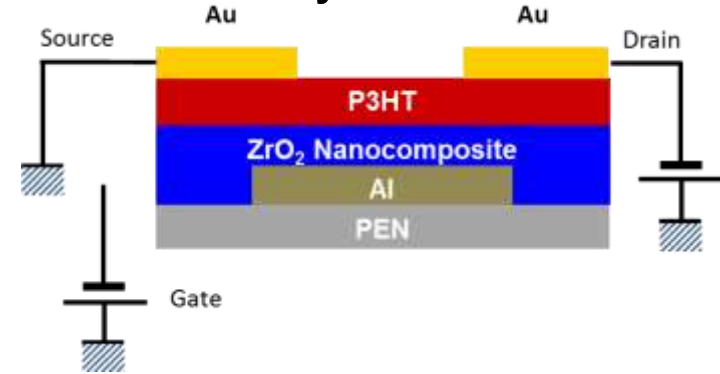
QD-Based LECs



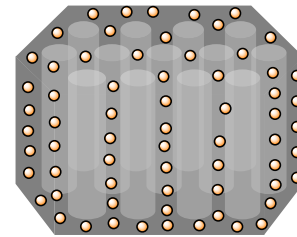
Photonics



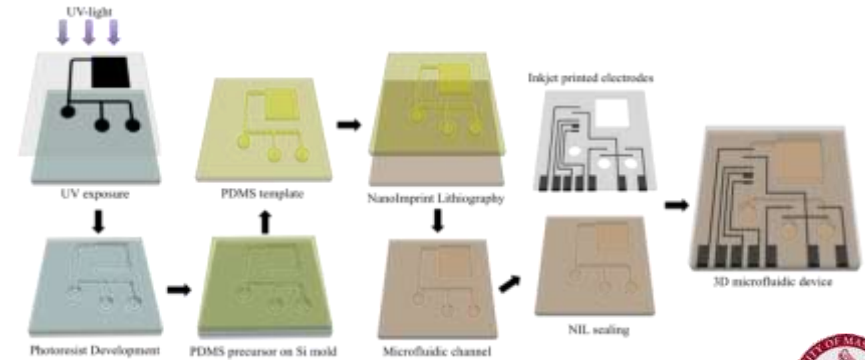
NP/Polymer Dielectrics



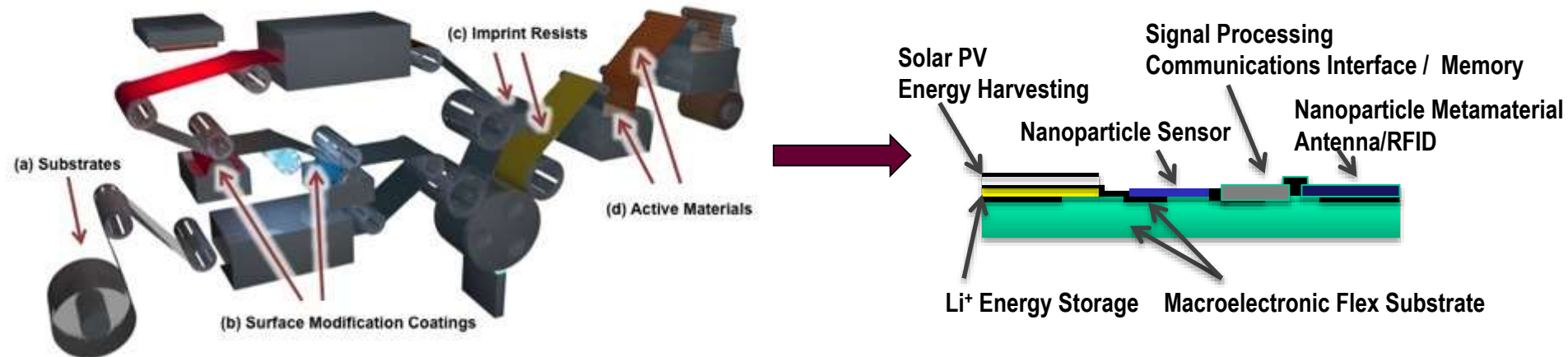
Nanostructured SuperCaps and Batteries



Printed Microfluidic Biosensors



One Solution: Low-Cost Capable Devices by Combining Printed Electronics and Nanostructured Device Layers



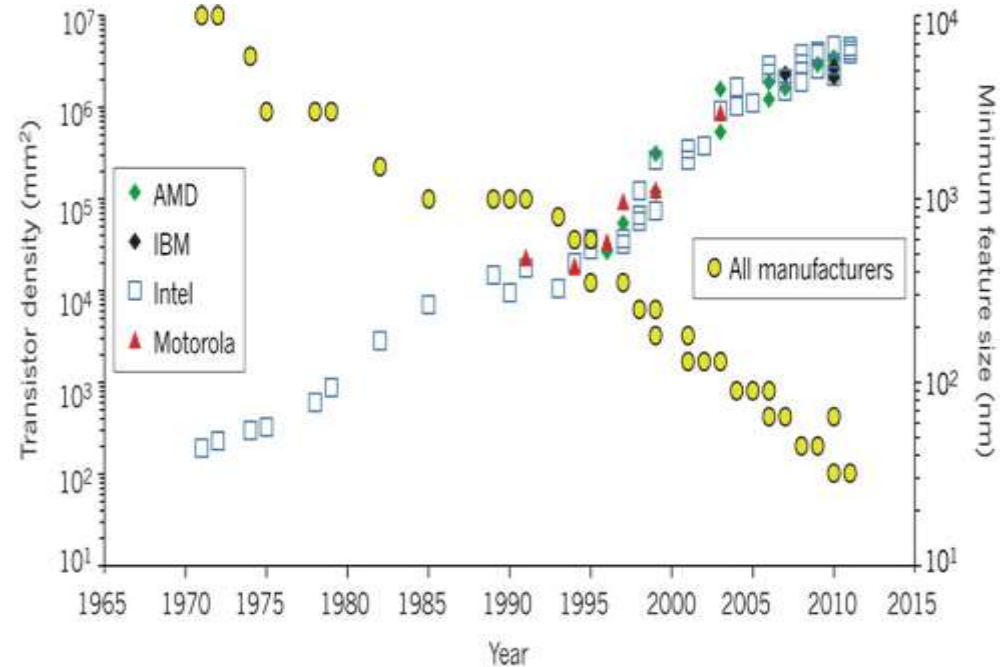
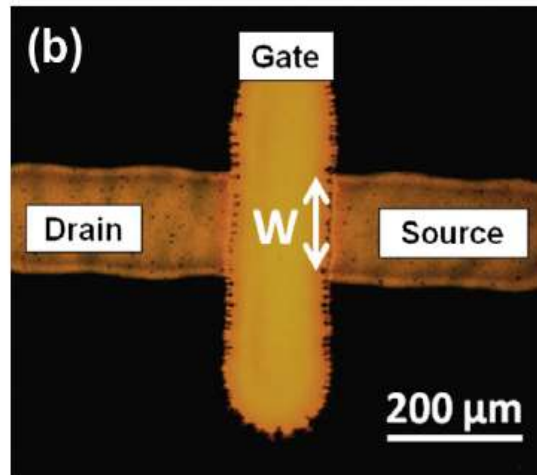
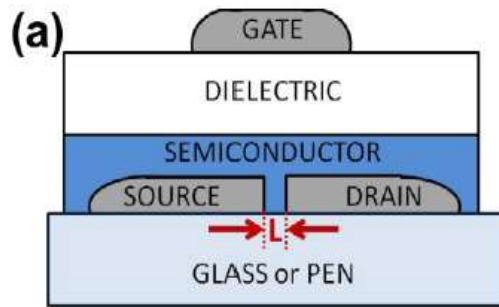
Challenges include:

1. Materials (mobility, lifetime, tune-able μ , ϵ , n)
2. Strategies for incorporation of inorganic device layers
3. Solution and additive-based processing
4. Increased integration density (smaller feature size)
5. Improved layer-to-layer dynamic alignment
6. Manufacturing tools and demonstration facilities

Next Generation Printed Electronics: One Fundamental Challenge is Integration Density

Ink Jet Printing / Laser Anneal

10s of Micron CDs = Pre 1970s Electronics

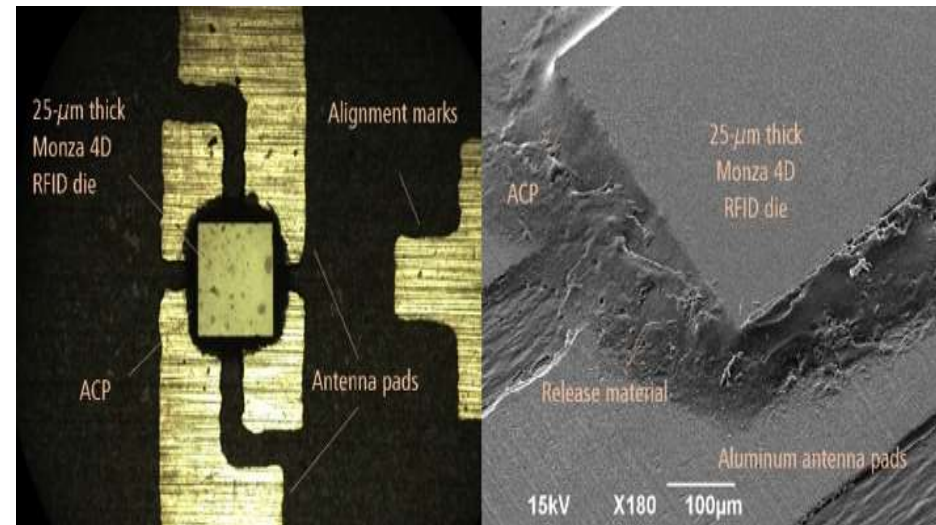
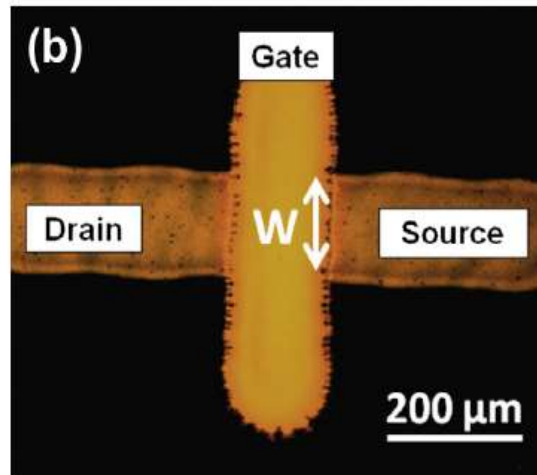
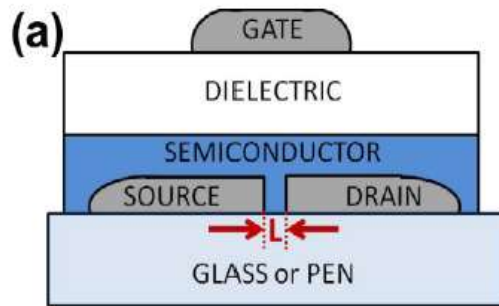


Microelectronic Engineering 111 (2013) 242–246

Next Generation Printed Electronics: One Fundamental Challenge is Integration Density

Ink Jet Printing / Laser Anneal

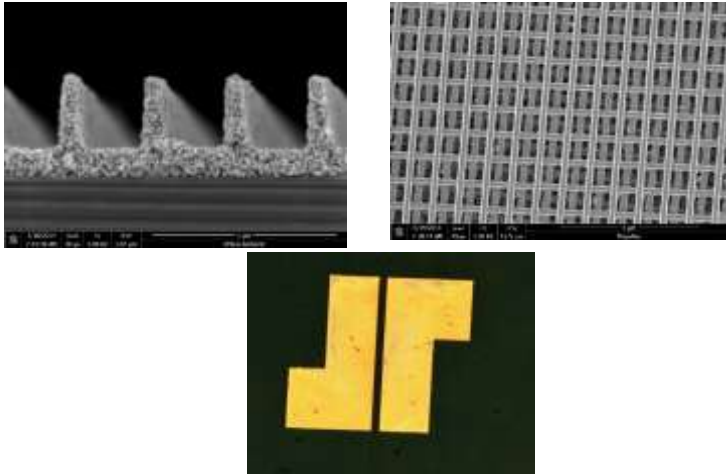
Near Term Issue: Sub-50 micron Contacts for Hybrid Integration



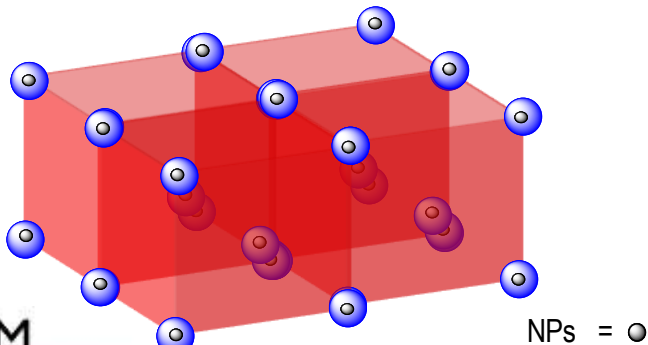
Microelectronic Engineering 111 (2013) 242–246

Our Tool Box: Materials, Device Layers, and Approaches

Nanoimprint Lithography Revisited: Direct "Printing" of 2-D and 3-D Hybrid and Inorganic Nanostructures



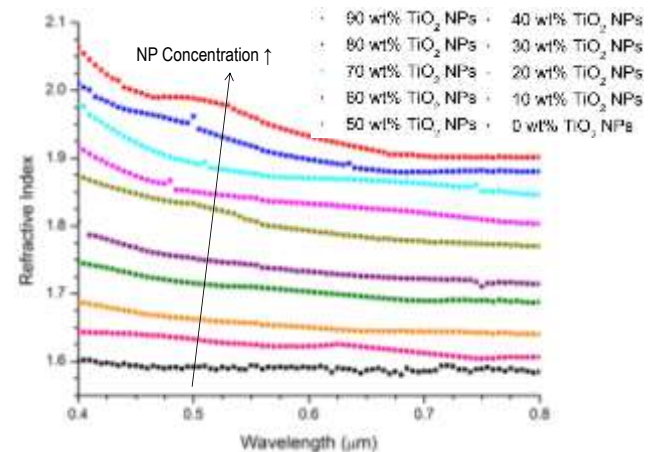
Periodic Nanocomposites and Metamaterials by Self-Assembly



Scalability: (R2R NIL, Ink Jet/Photonic, Hybrid Coating, Pick and Place, more)



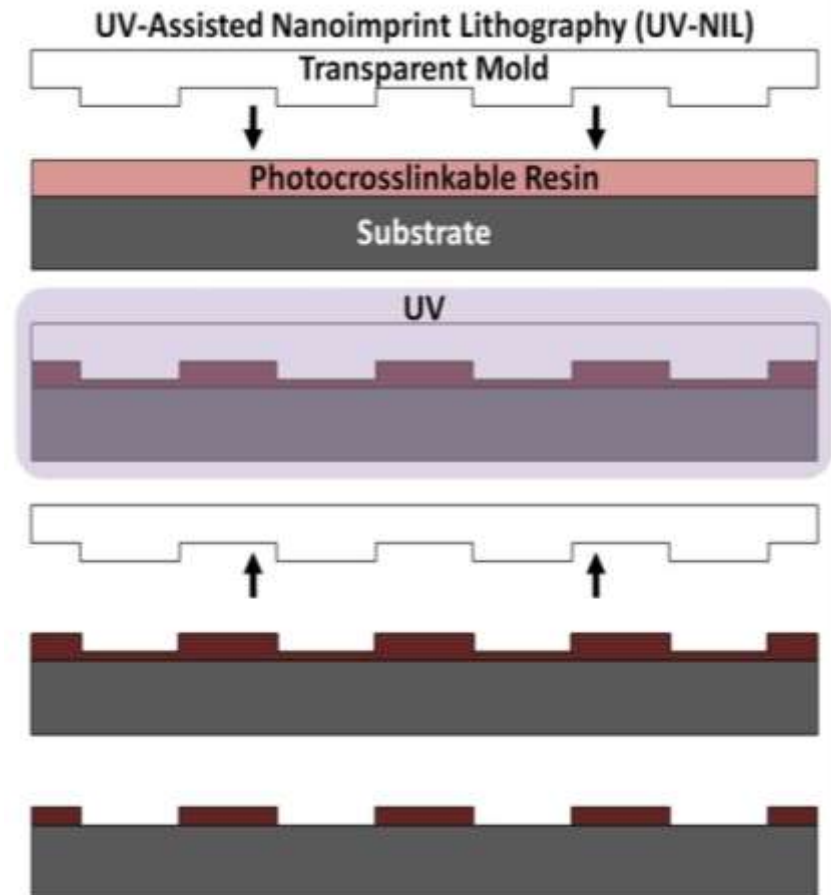
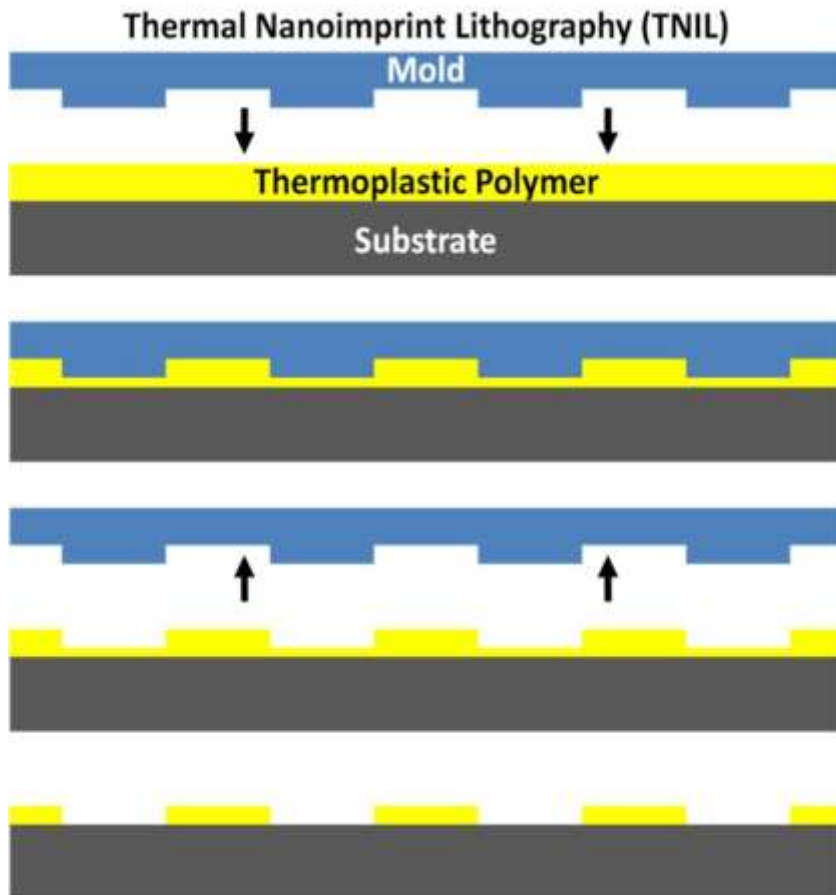
Tunable Hybrid Materials



Nanoimprint Lithography: Two Modes

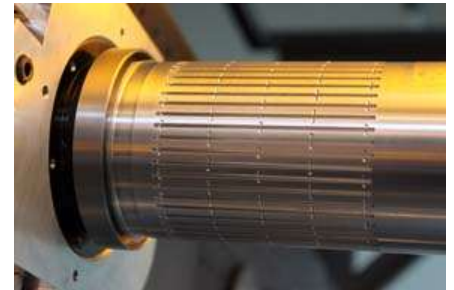
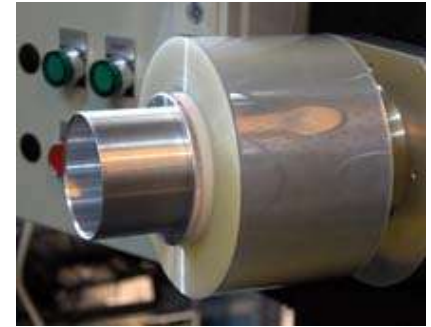
Thermal: Emboss thermoplastic or thermoset using heat, pressure

UV-Assisted: Contact UV-curable resin with master, photocure

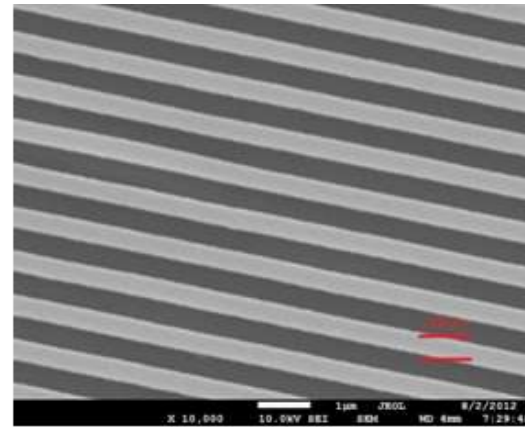
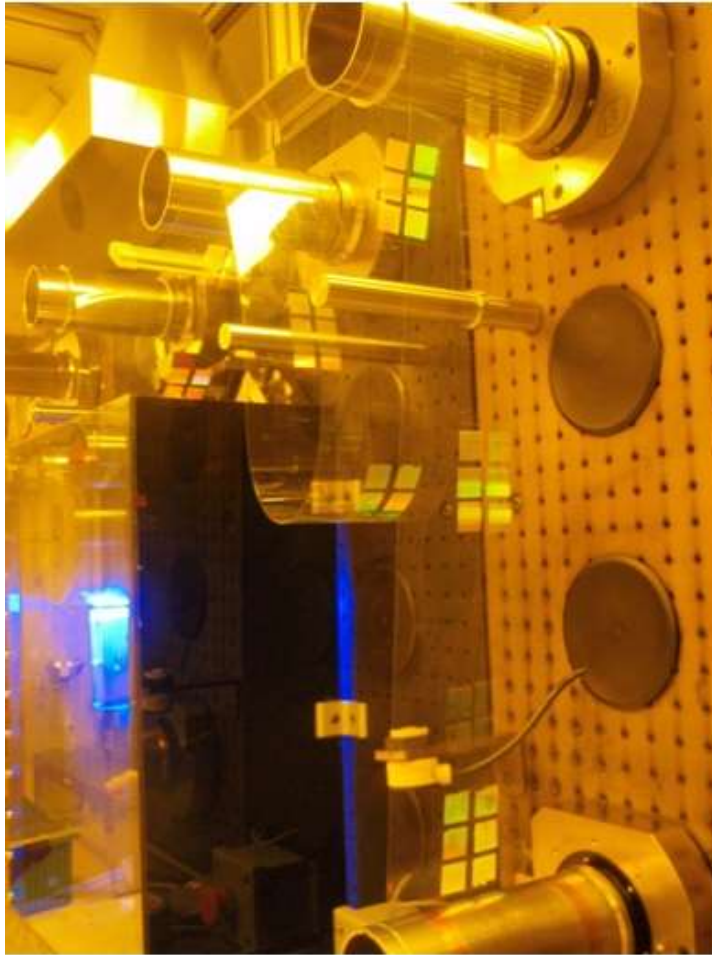


UMass / CHM R2R NIL Tool

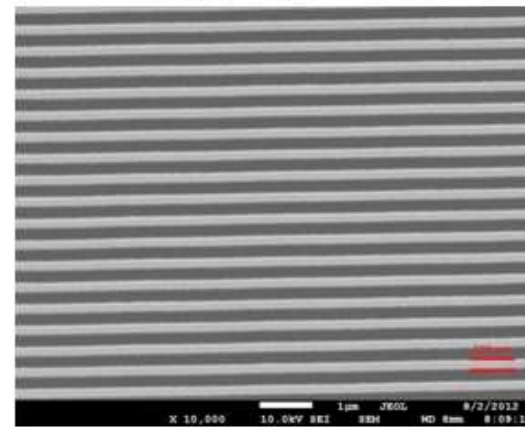
UMass NANOemBOSS R2RNIL constructed with Carpe Diem Technologies (Franklin, MA)
Prof. Ken Carter and Jonathan Rothstein Test Bed Coordinators



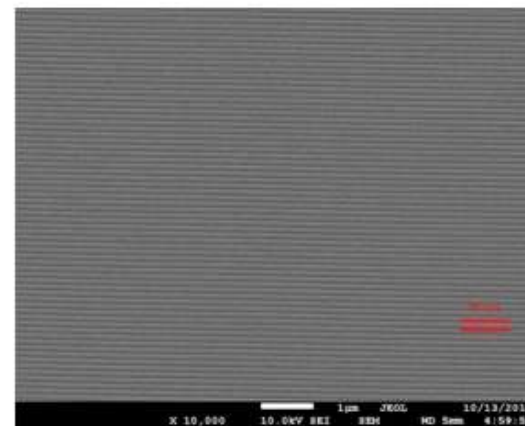
R2RNIL – 500 nm to Sub-100 nm Gratings



500 nm



230 nm



70 nm

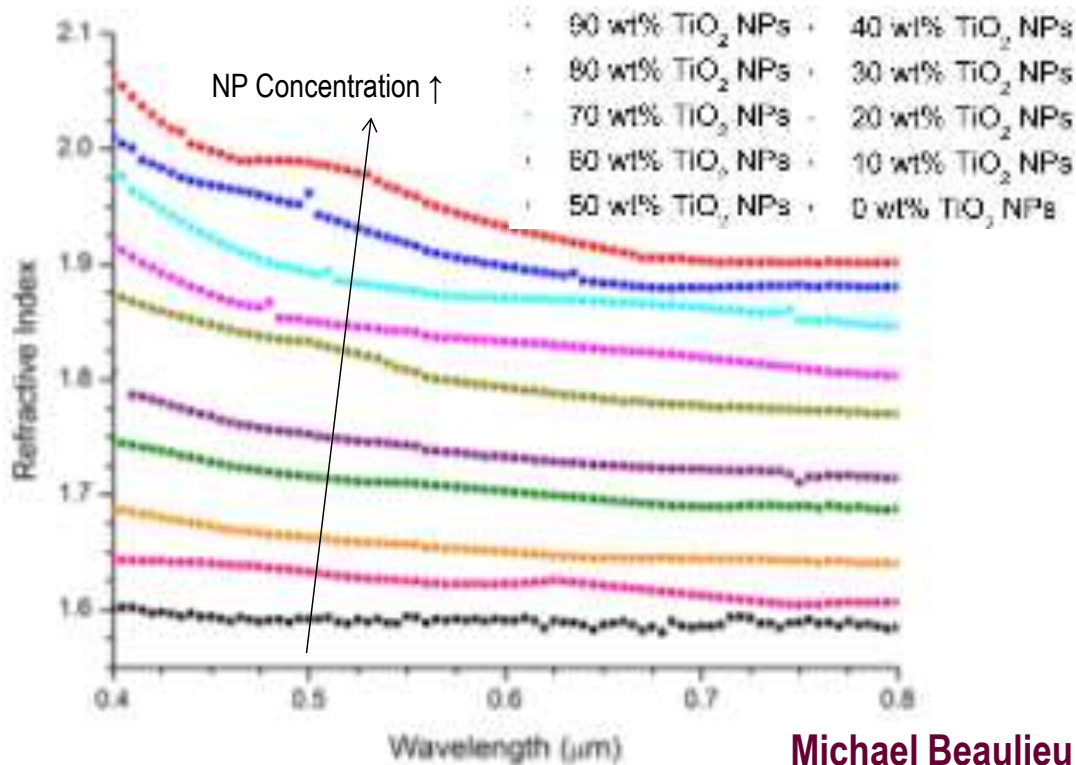
John, Tang, Rothstein, Watkins., *Carter Nanotechnology*, 2013,

NIL - Intermediate Assessment

- **NIL Offers Very High Pattern Resolution**
- **R2R NIL Offers High Rate Continuous Patterning**
- **Current NIL Resists Offer Limited Functionality**
- **Can We Imprint Directly into Useful Materials?**

Polymer / TiO₂ NP Hybrid Resists with Tunable Refractive Index

- Anatase NPs 5-25 nm / smooth films
- RI Measured with VASE, films thicknesses 150 nm to 350 nm
- RI Manipulation with Excellent Transparency
- RI Matching for Transparent Composites / RI Tuning for Light Management

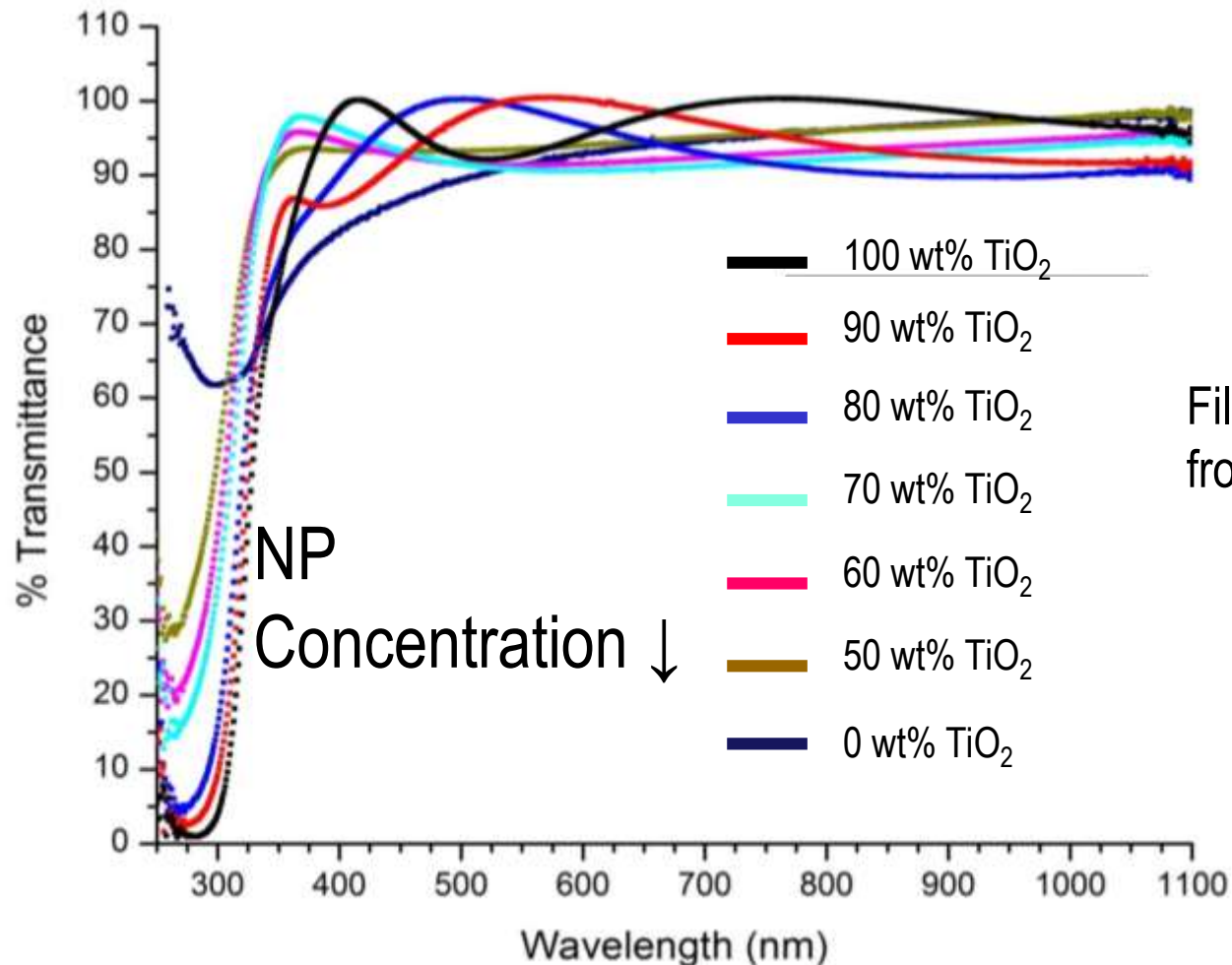


Michael Beaulieu et al., ACS Photonics 2014

% TiO ₂ Nanoparticles	50	60	70	80	90
RMS (nm)	5.41	5.10	4.85	4.70	4.97

Transmittance of Planar Nanocomposites

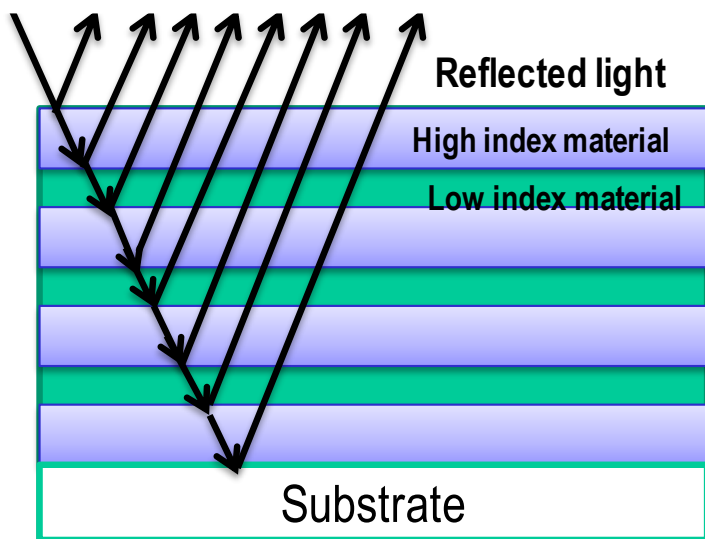
- The planar nanocomposite films are greater than 90% transparent from 400 nm to 800 nm



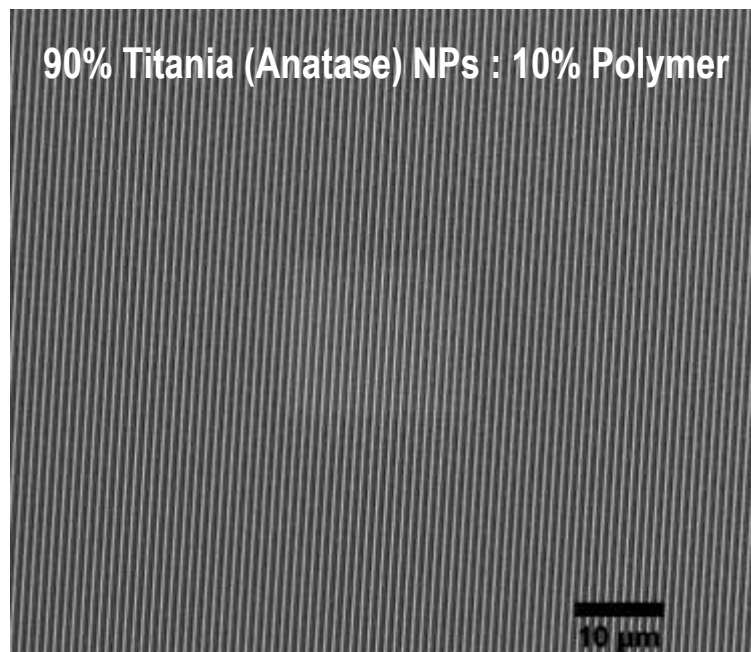
Solution Coatable Patterned and Planar Hybrid Device Layers

Example: Tuned Material Properties, Patterns by Nanoimprint Lithography

Wavelength Selective Bragg Mirrors



NIL Patterning of Composites



U.S. Appl. 13/900,248

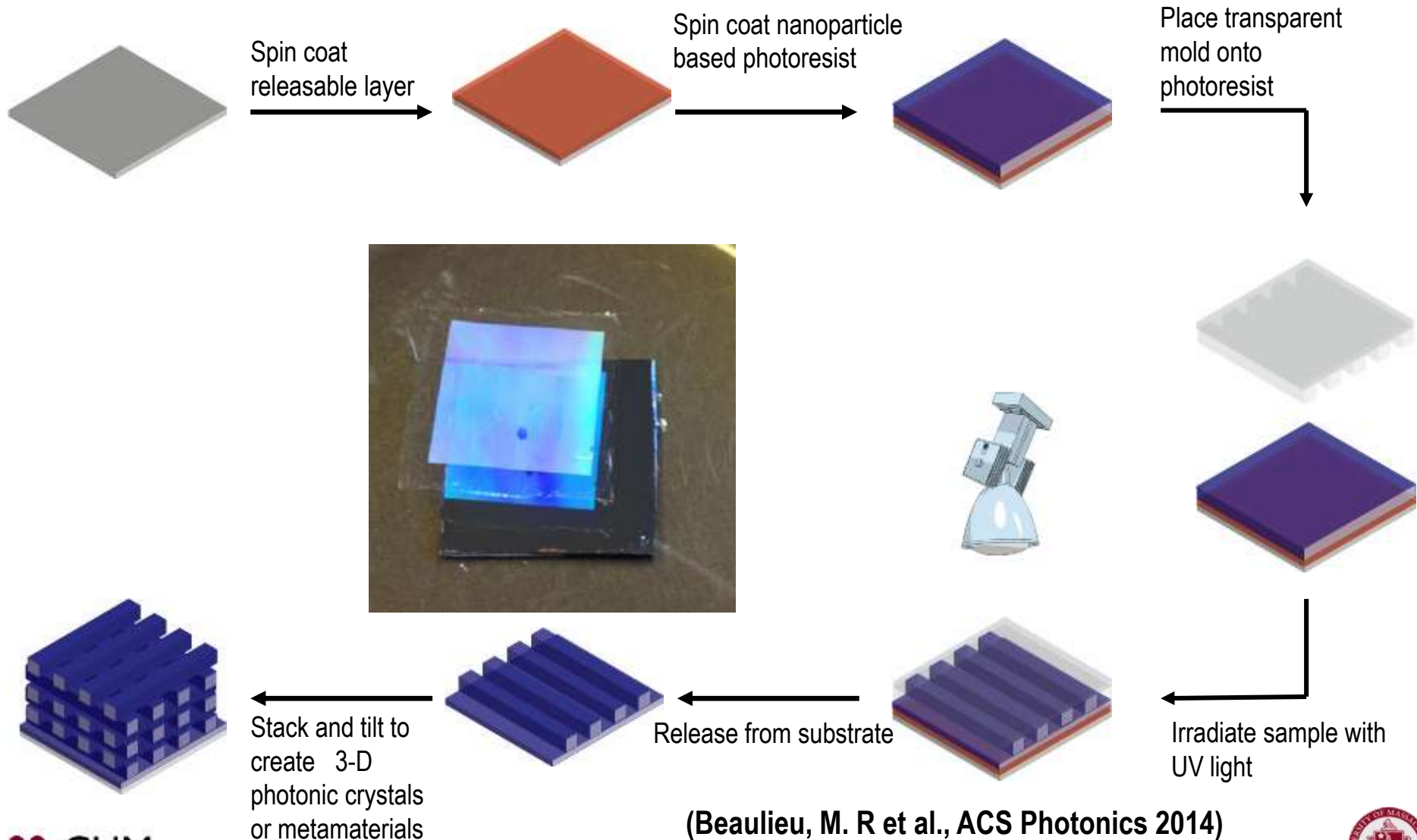
We can create, coat and pattern smooth polymer/NP and NP films

Ranging from 100% polymer to 90% stabilized NPs

metal oxides/high k /high RI / low RI

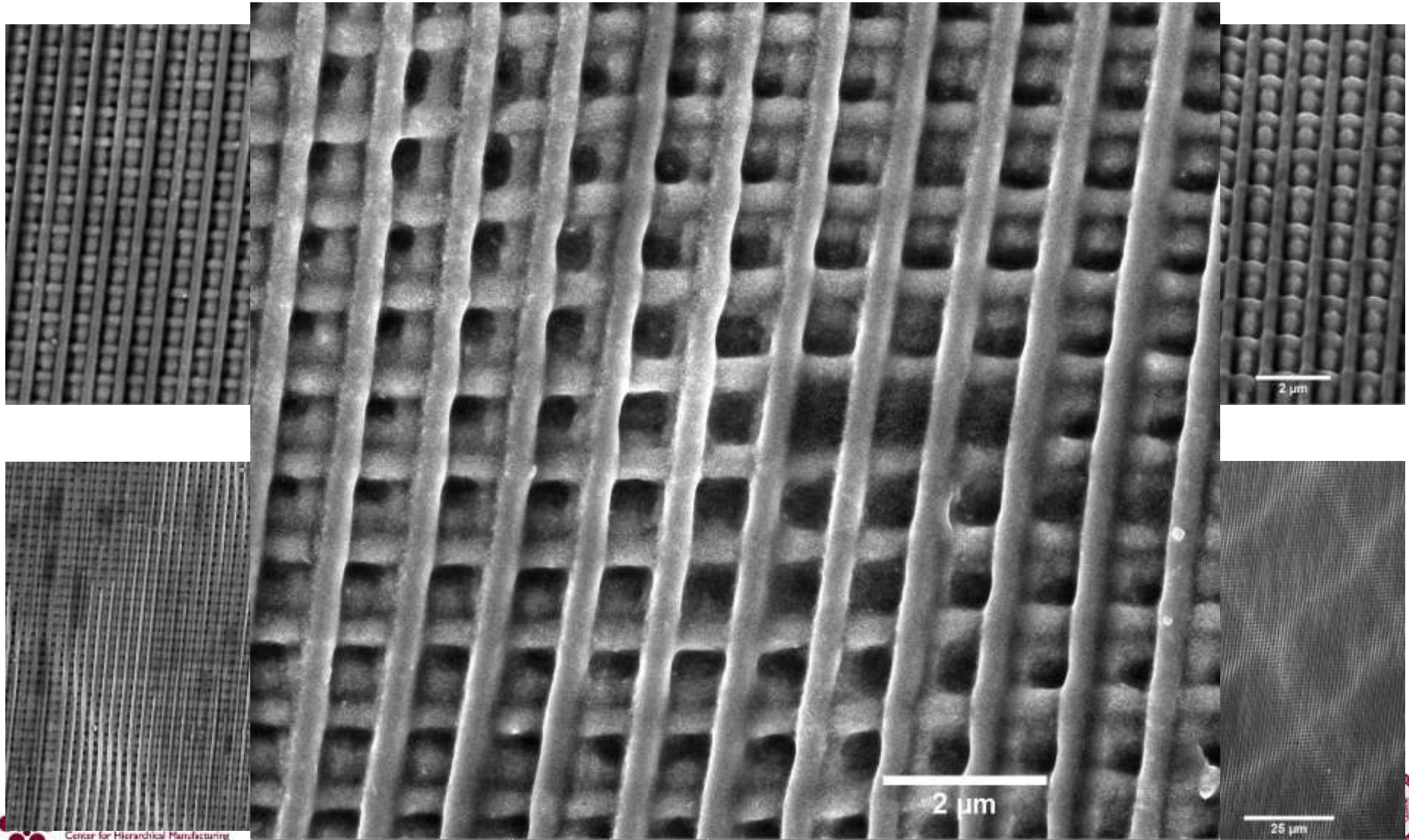
Crystalline NPs / structures –Low Temperature Processing

3-D Patterning of Nanocomposites Print-Lift-Turn-Stack



3D Patterning: Tetralayer

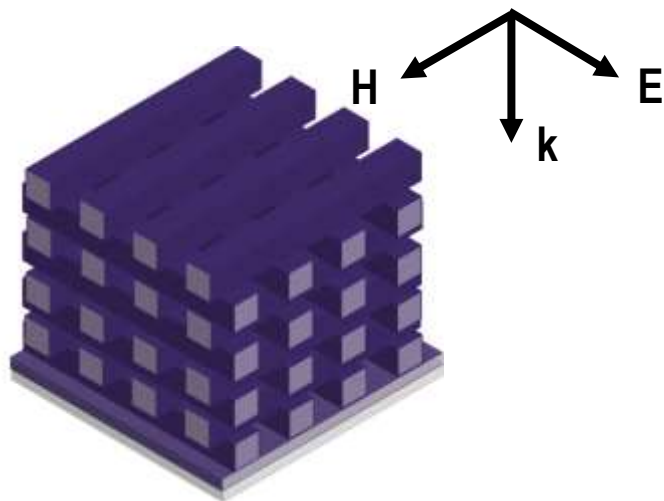
- SEM Images: 50% TiO₂, 50% NOA60



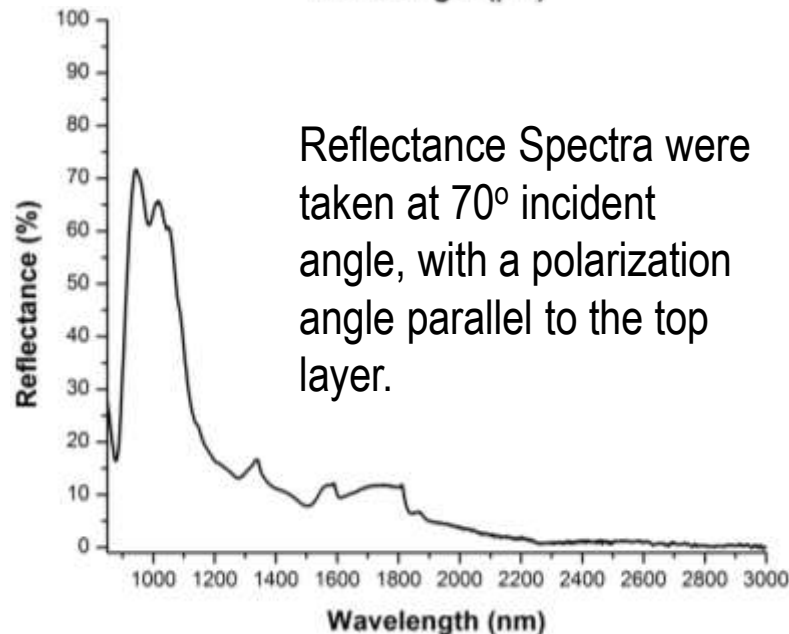
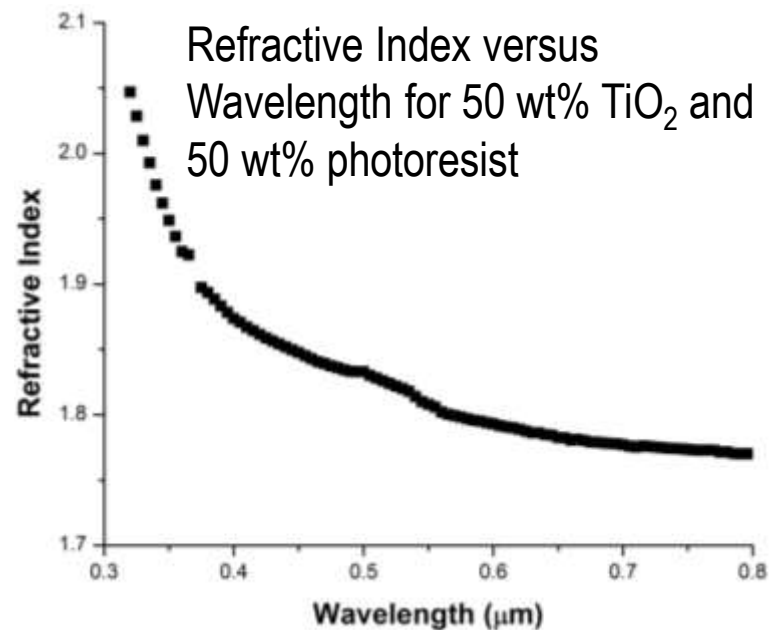
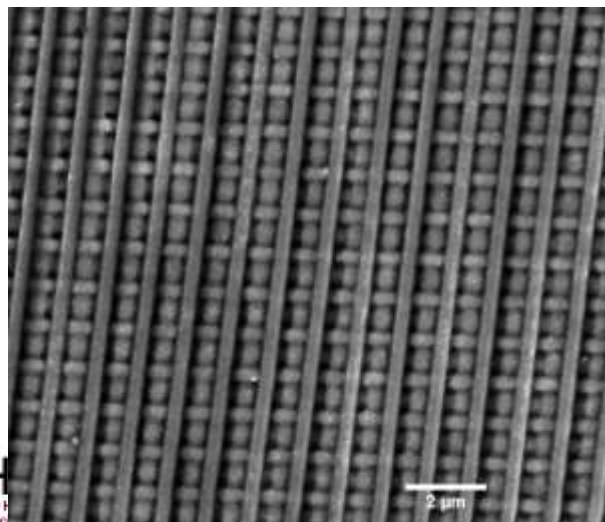
Printable Photonic Log Pile Structures

(Beaulieu, M. R et al., ACS Photonics 2014)

6-layer Photonic crystal made from 50 wt% anatase TiO₂ nanoparticles and 50 wt% photoresist

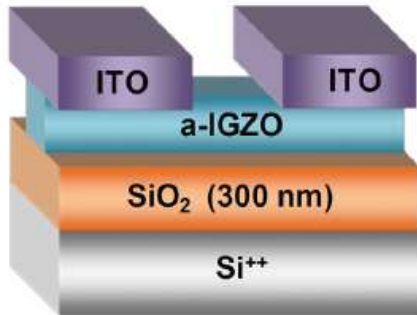


Top Down SEM View



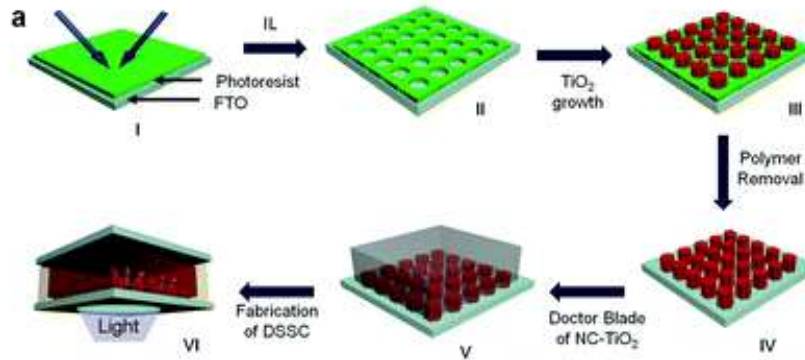
Direct Imprinting of Patterned Metal Oxides Nanostructures

Patterned ITO for transistors



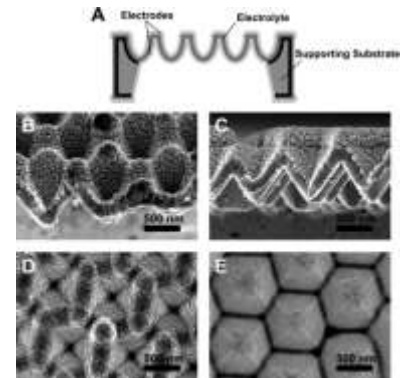
ACS Appl. Mater. Interfaces
2012, 4, 1614-1619

Patterned TiO₂ for solar cells



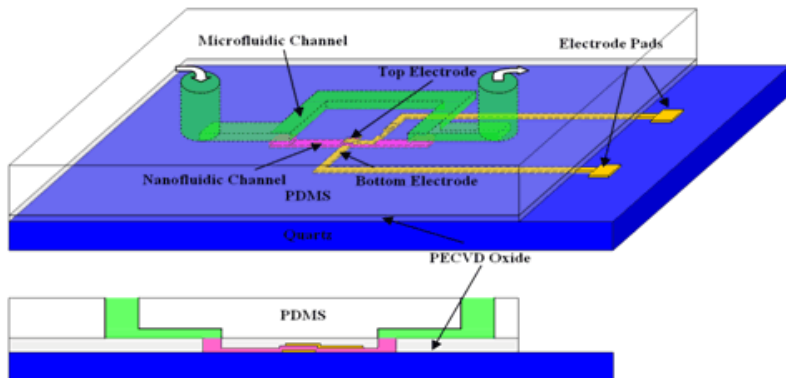
Nanoscale, 2012, 4, 4464

Patterned YSZ for SOFC

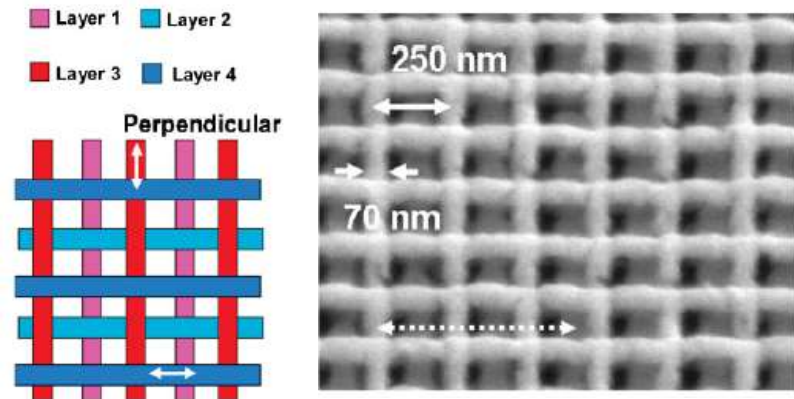


ACS Nano, 2011, 5, 5692-5696

Patterned electrodes for nanofluidics

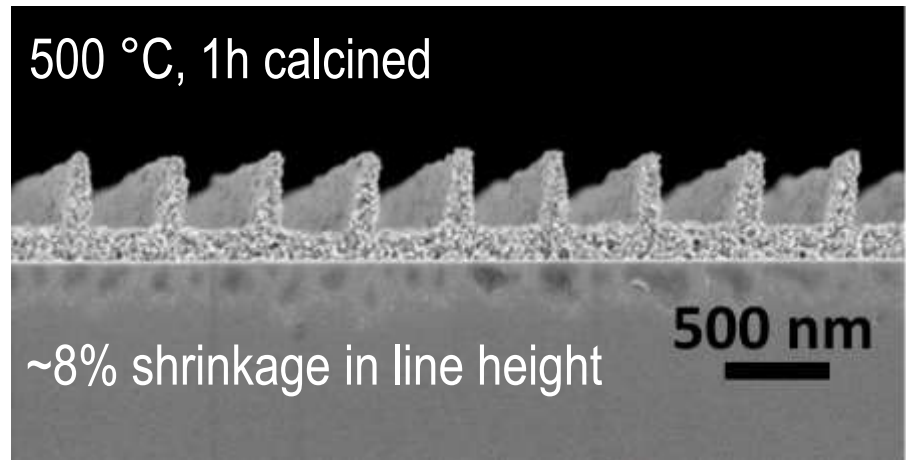
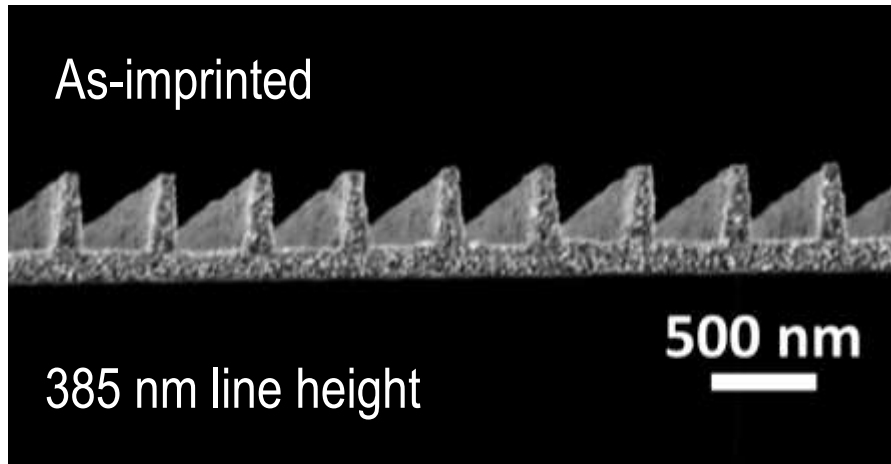
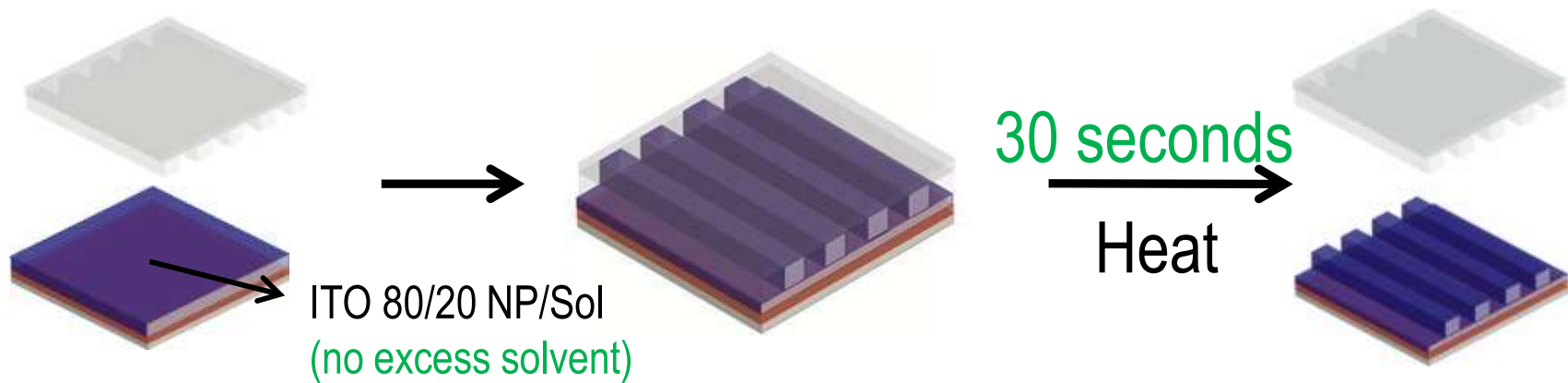


Patterned dielectrics for photonic devices

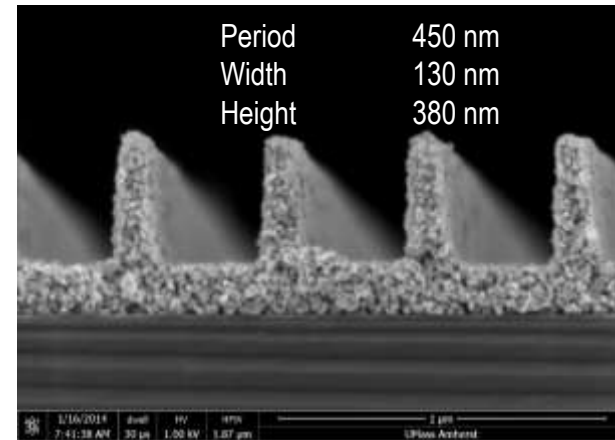
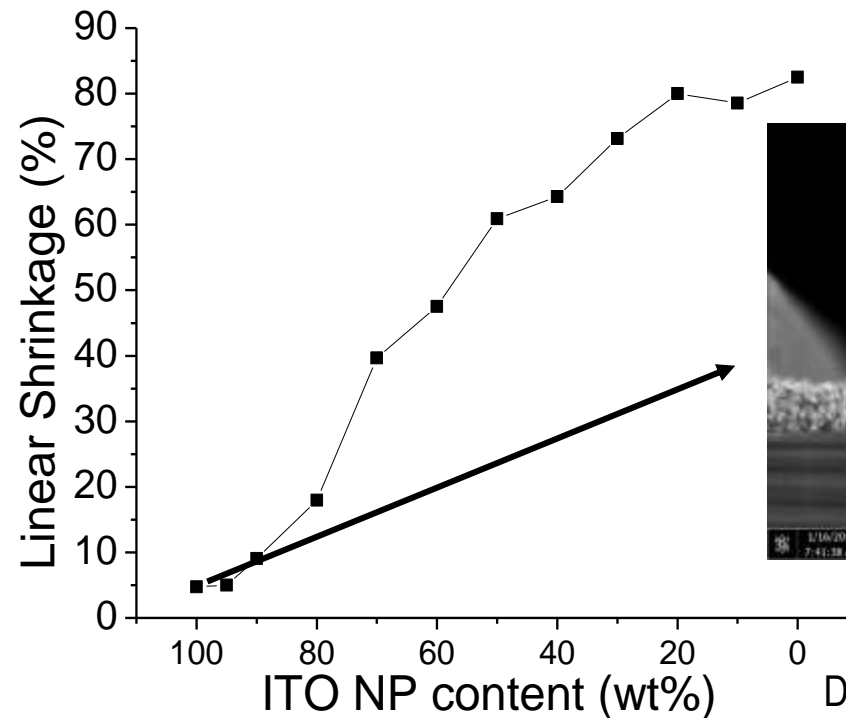
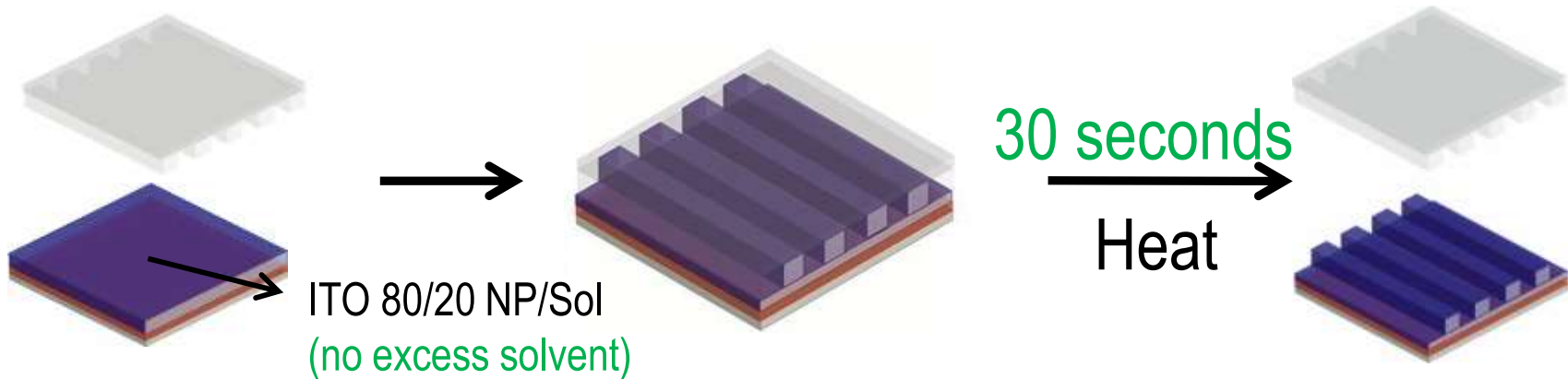


Adv. Mater. 2010, 22, 487-491

Direct Imprinting of ITO NP/Sol Ink

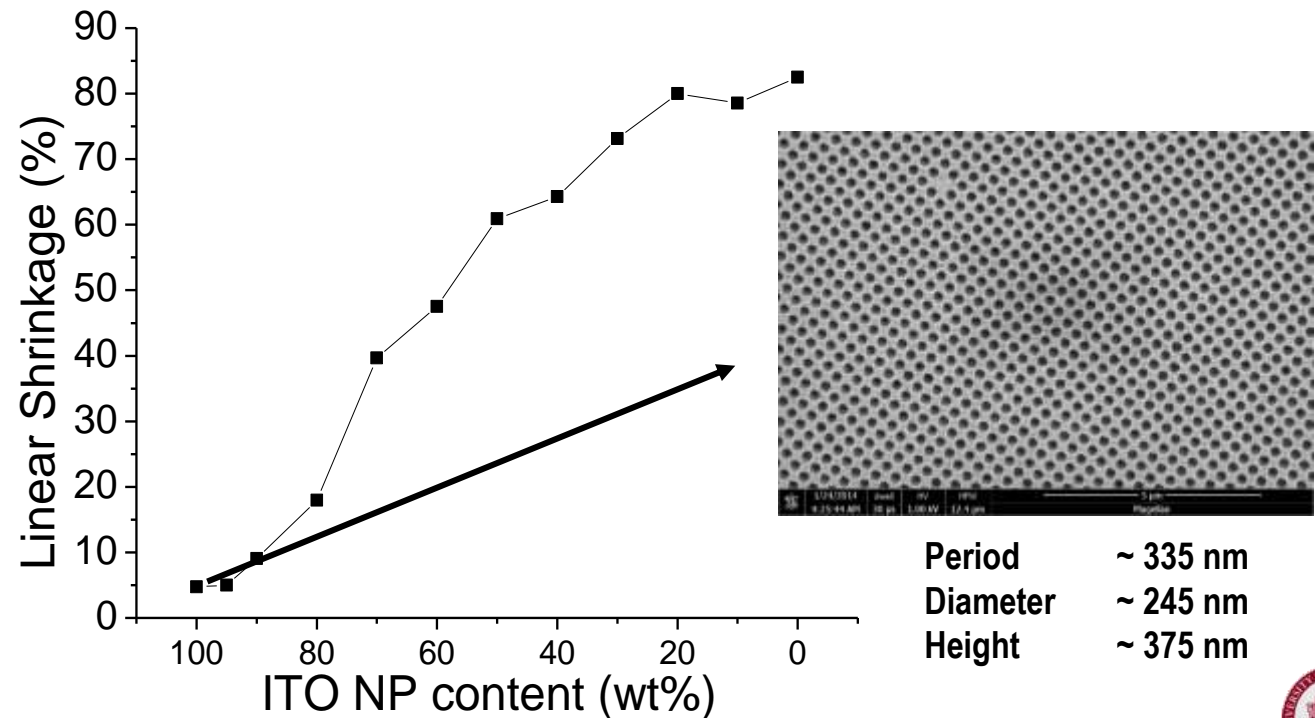
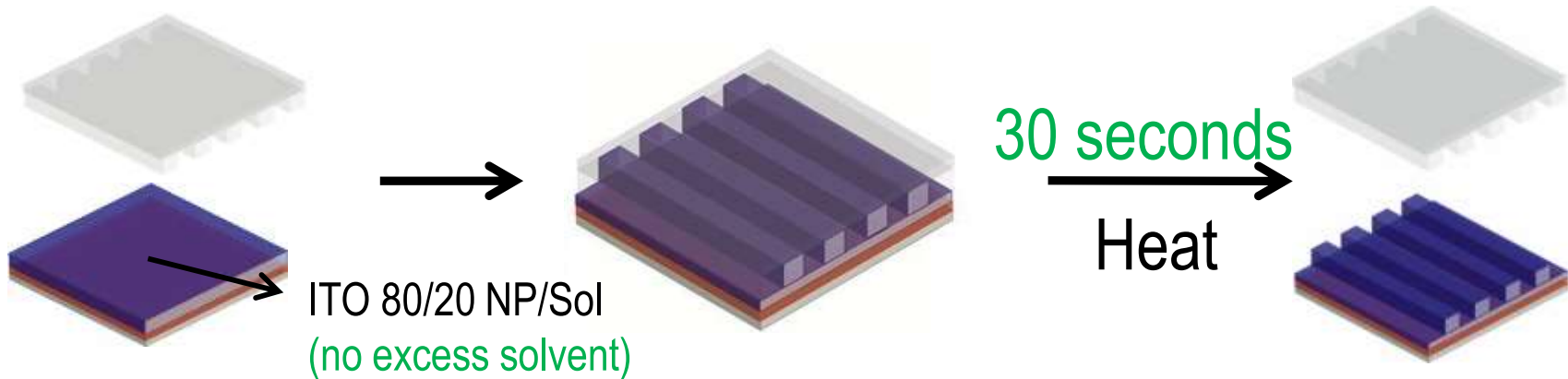


Direct Imprinting of ITO NP/Sol Ink

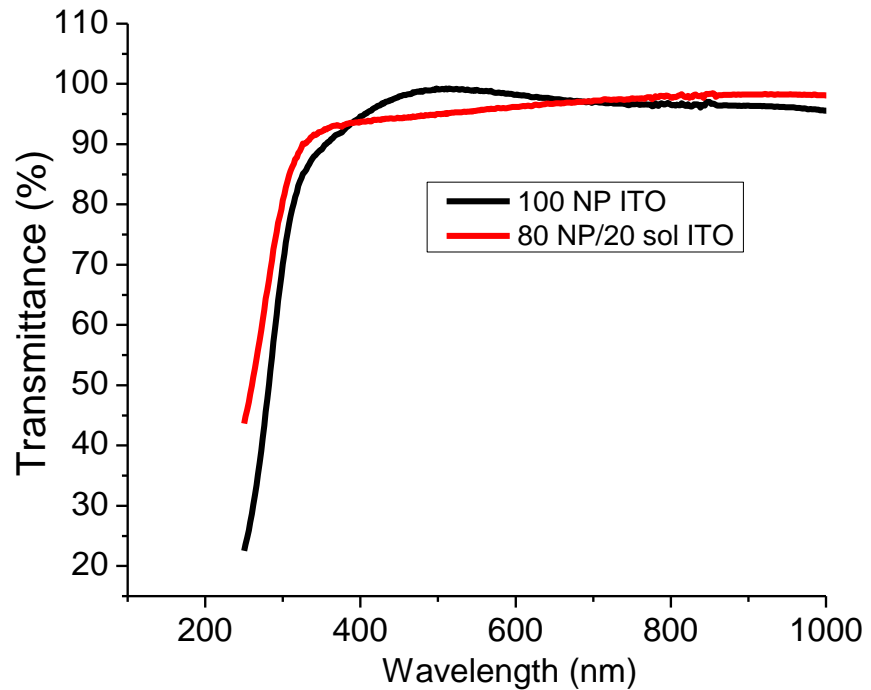
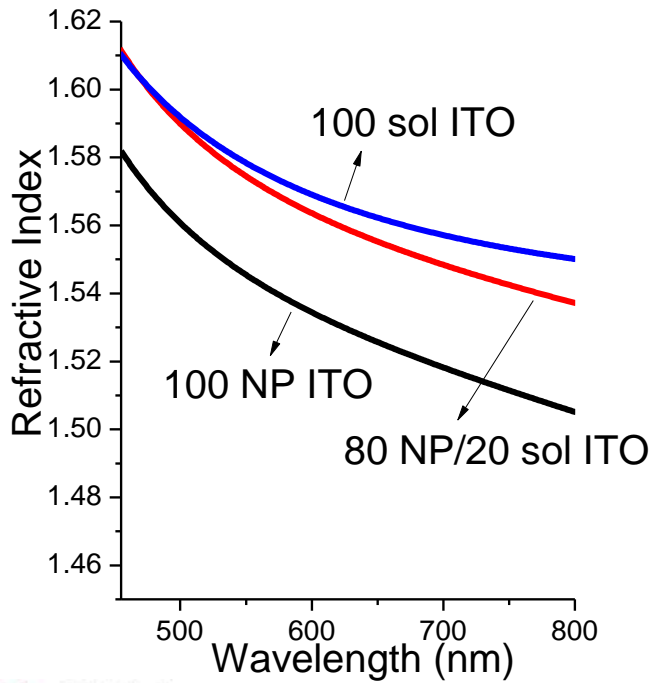
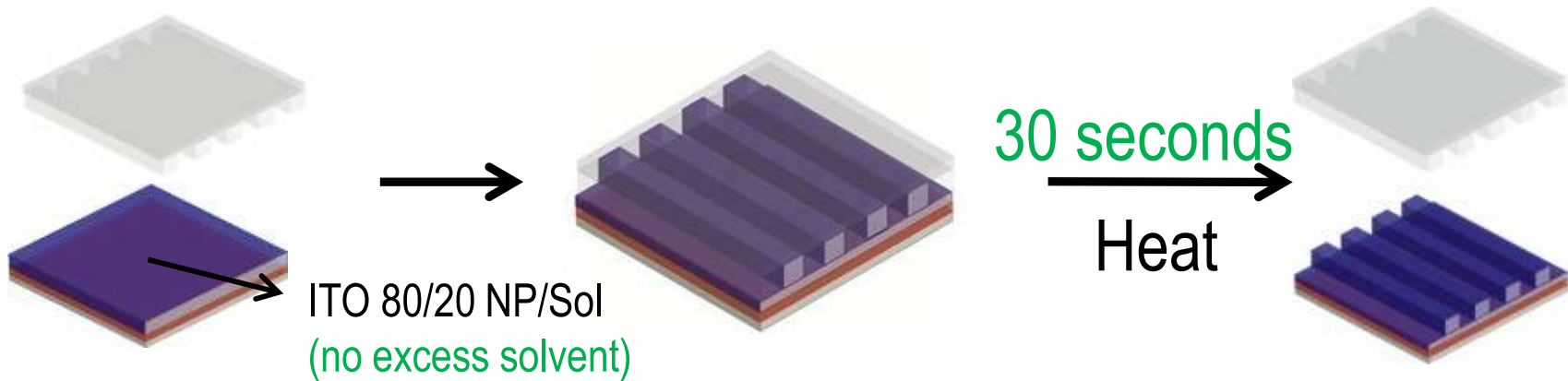


Dried at R.T.
Calcined at 500 °C

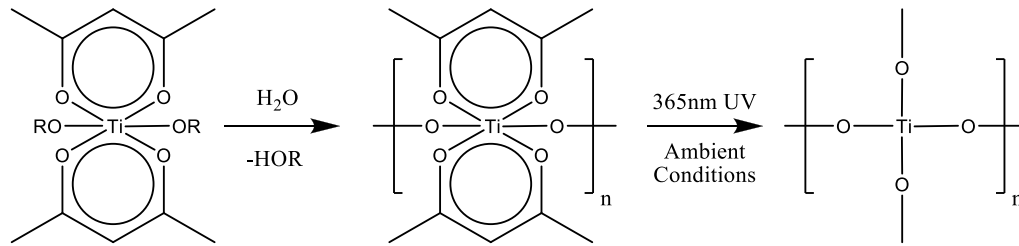
Direct Imprinting of ITO NP/Sol Ink



Direct Imprinting of ITO NP/Sol Ink

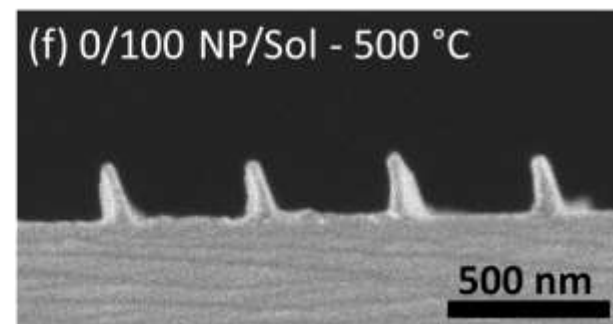
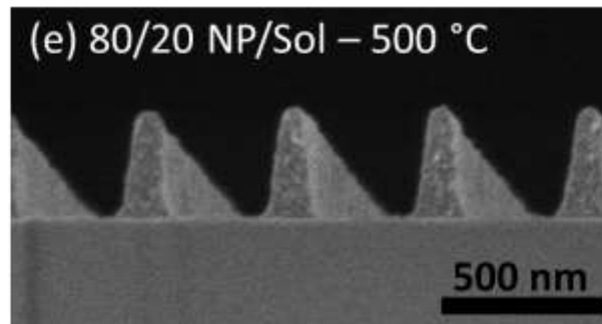
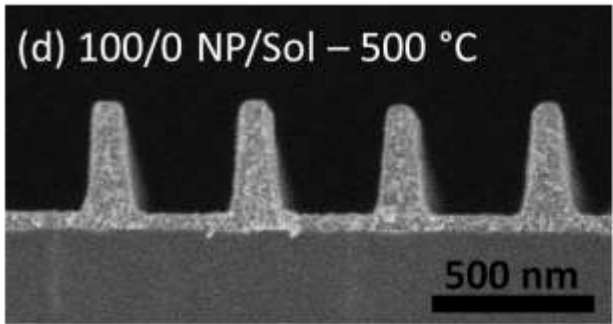
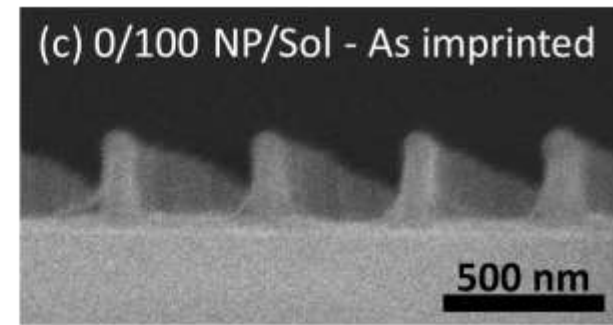
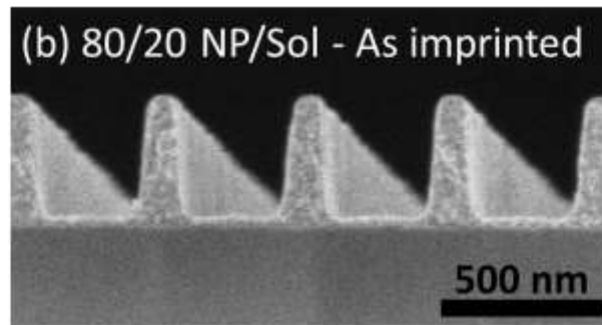
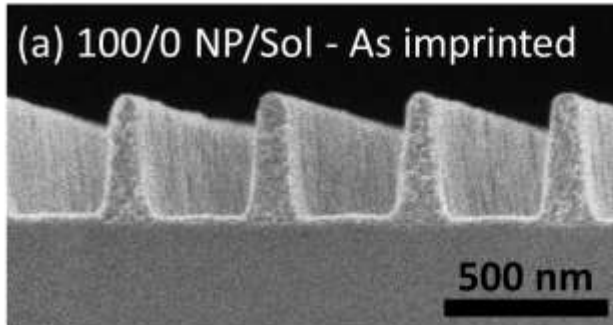


Soft-nanoimprinting of TiO₂ Nanostructures



TiO₂ nanoparticles (anatase)

UV curable TiO₂ sol-gel precursor



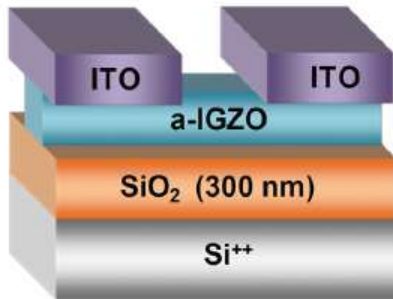
5% Shrinkage

11% Shrinkage

50% Shrinkage

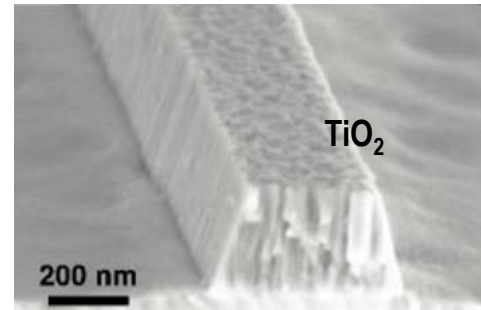
Is Residual-layer Free Imprinting for Device Fabrication Possible?

Printed Transistors



ACS Appl. Mater. Inter. **2012**, 4, 1614

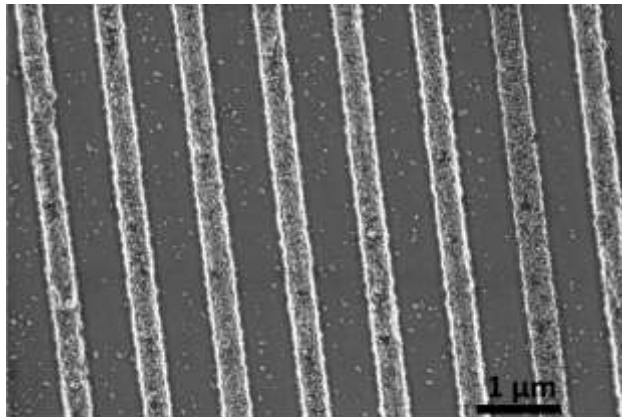
Waveguides by E-beam and Etch



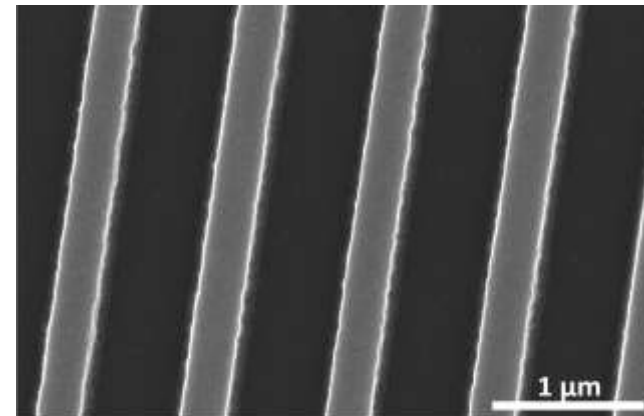
Optics Express **2012**, 20, 23821

Yes, Isolated Metal Oxide Lines

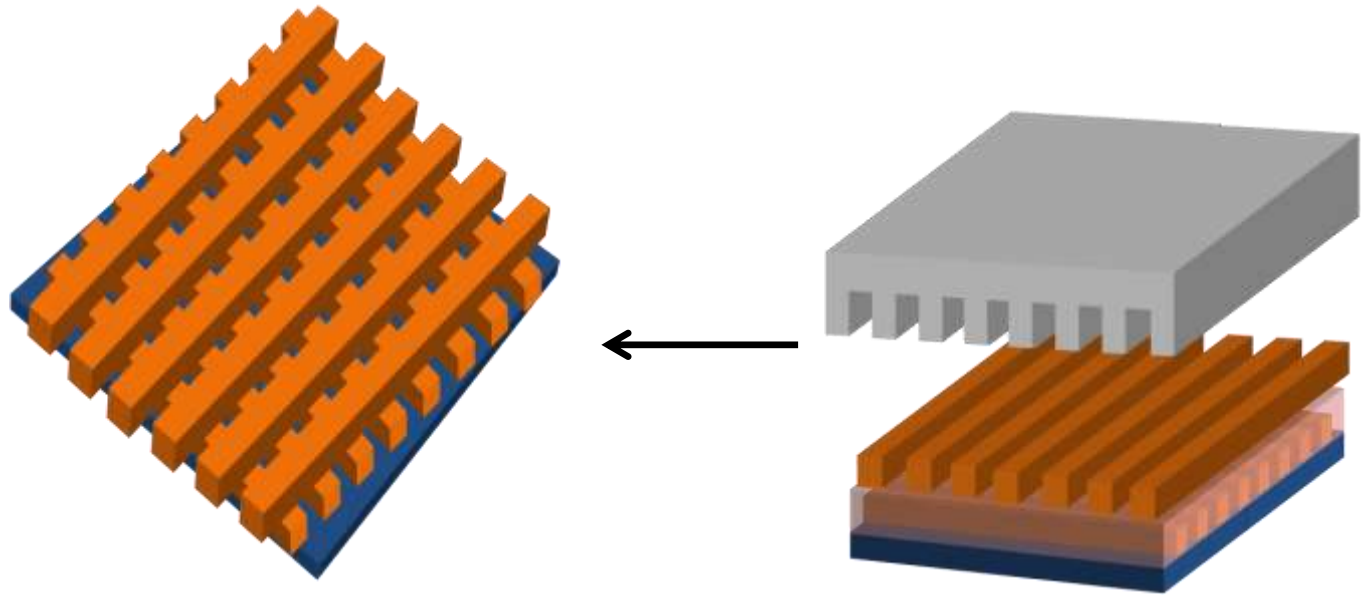
ITO



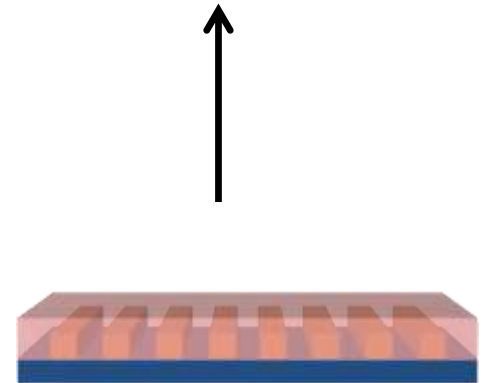
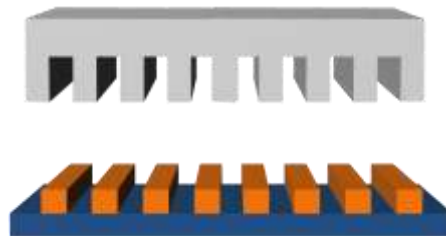
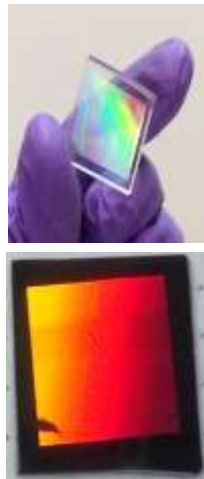
TiO₂



All Inorganic 3D Nanoimprinting



3D inorganic metal oxide nanostructures

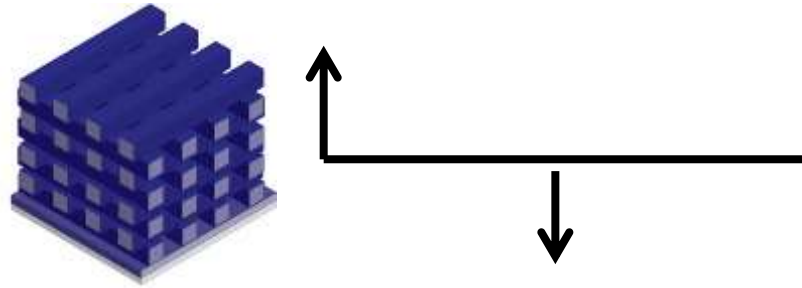


Planarized using crosslinkable polymer

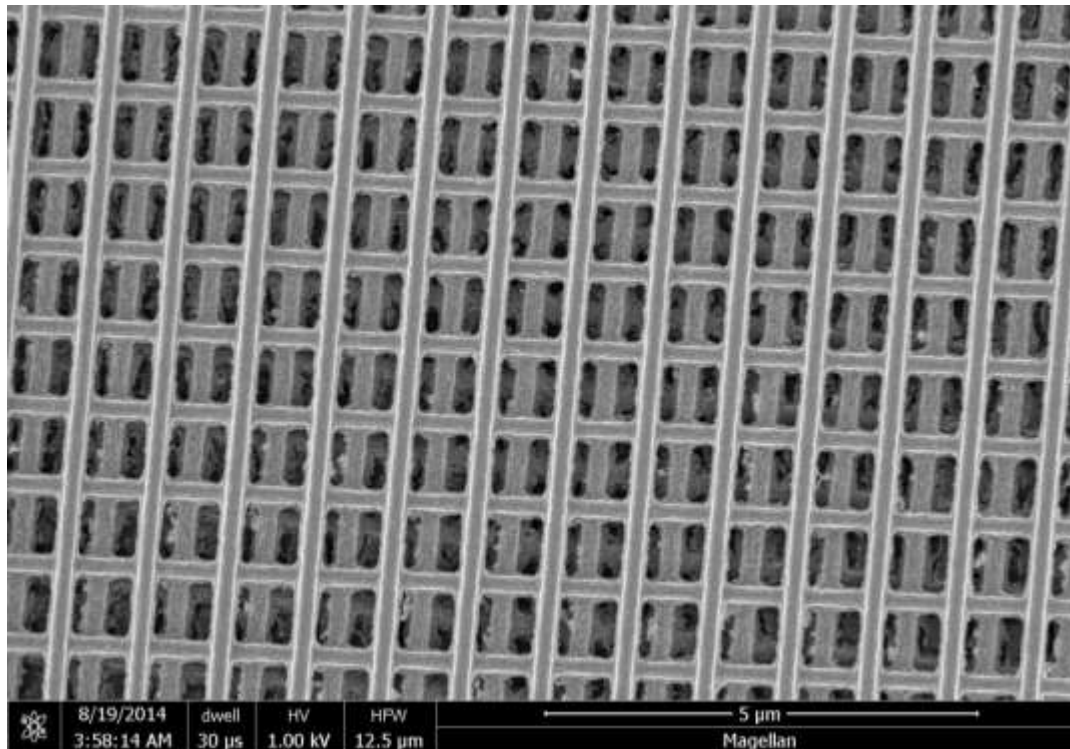
R. Khotari, I. Howell

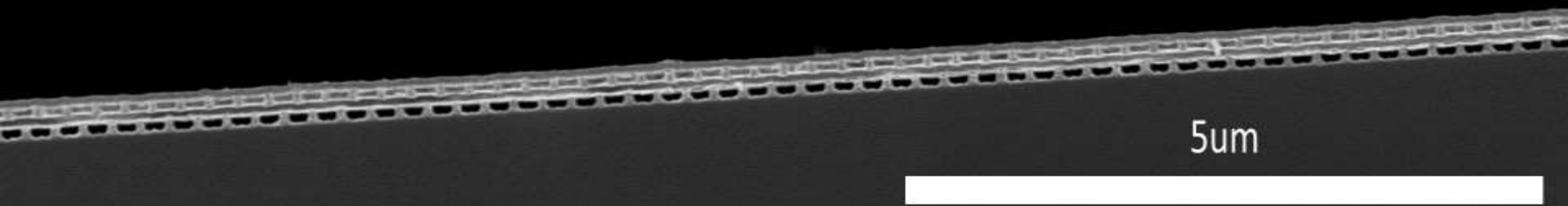
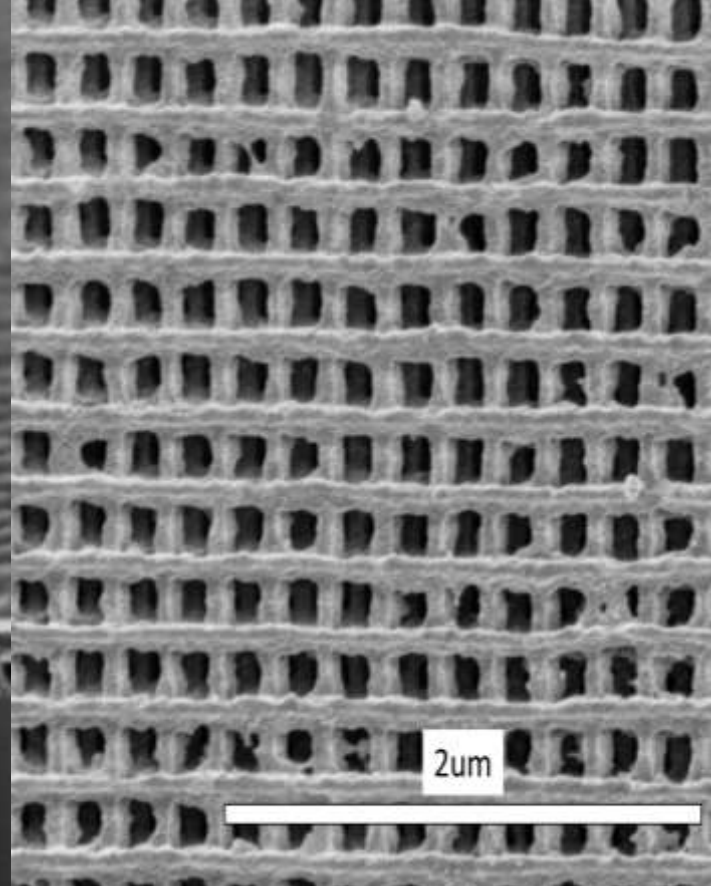
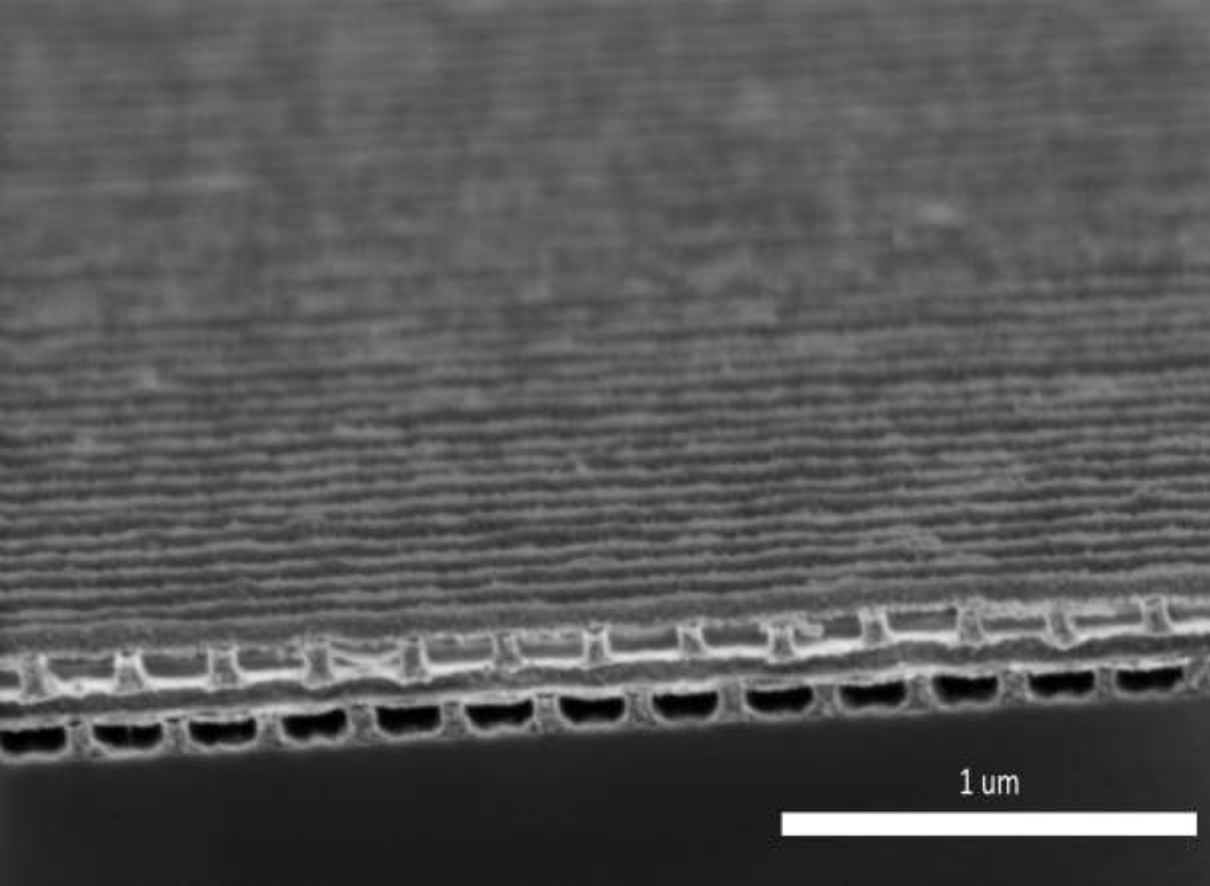
Layer by Layer Printing of Crystalline Metal Oxides

Pattern TiO_2 using NIL \rightarrow Planarize using polymers



Remove planarizing layer at the end by calcination





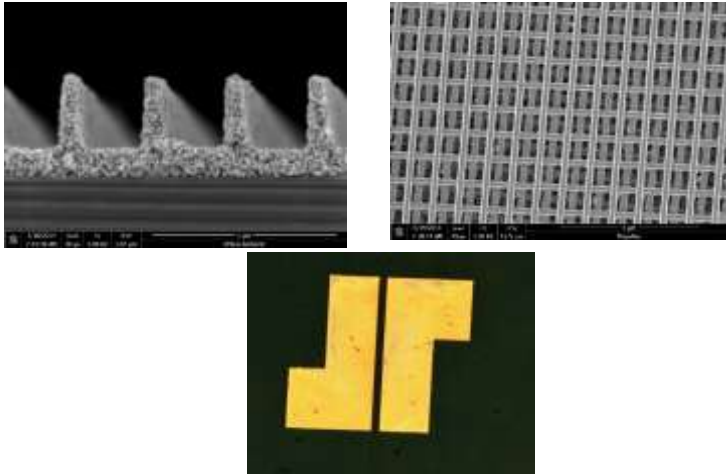
Direct “Imprinting” of Patterned Crystalline Metal Oxide and Metal Films for Devices

Potential Impacts

- Direct Printing of Inorganic Devices
- Have Demonstrated Conductors and Dielectrics
- Avoid Performance Limitations of Printed Organic Devices
- R2R Platform, Additive
 - low cost alternative to traditional Fabs
- Combine with Pulse Flash Lab Cure for Low T Substrates
- Versatile: Transistors to Fuel Cells
- Bring High Integration Density to Printed Systems

Our Tool Box: Materials, Device Layers, and Approaches

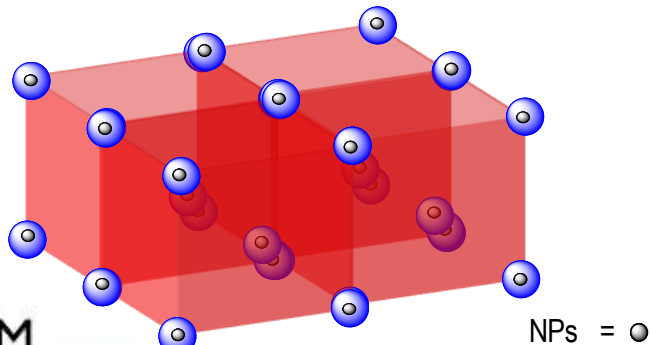
Nanoimprint Lithography Revisited:
Direct "Printing" of 2-D and 3-D Hybrid and
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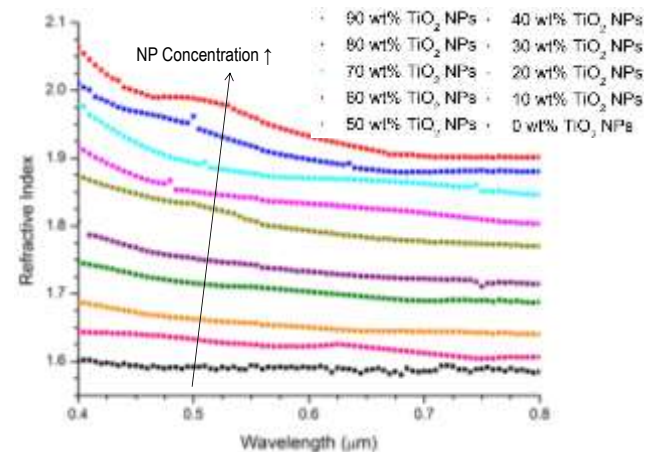
Scalability: (R2R NIL, Ink Jet/Photonic,
Hybrid Coating, Pick and Place, more)



Periodic Nanocomposites
and Metamaterials by Self-Assembly

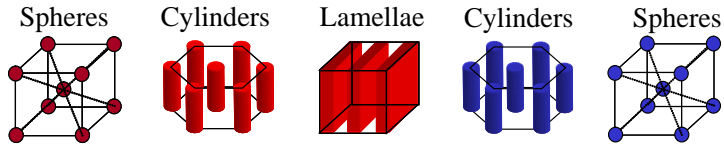
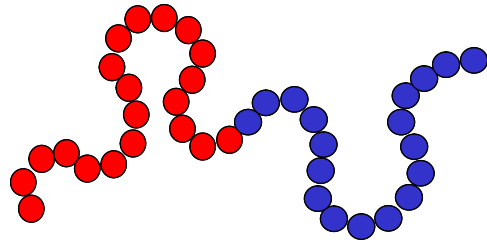


Tunable Hybrid Materials

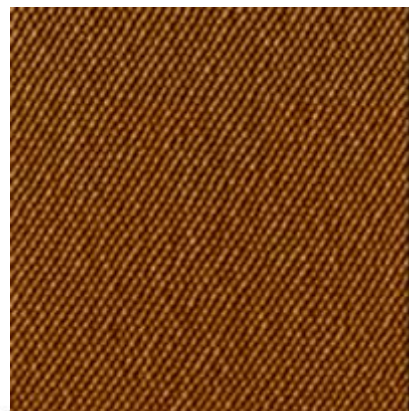


Block Copolymer Templates: Spontaneous Assembly upon Spin Coating, Complete Control of Morphology

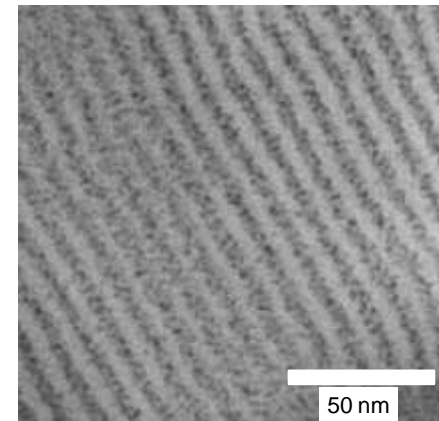
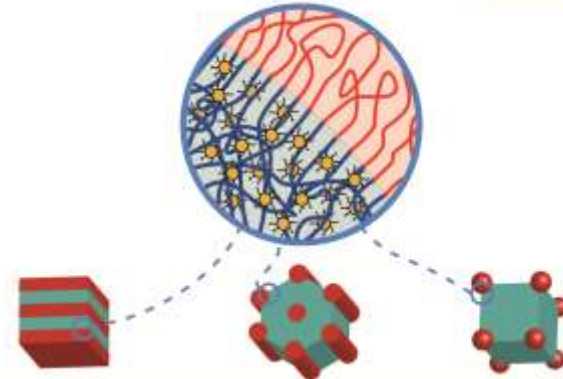
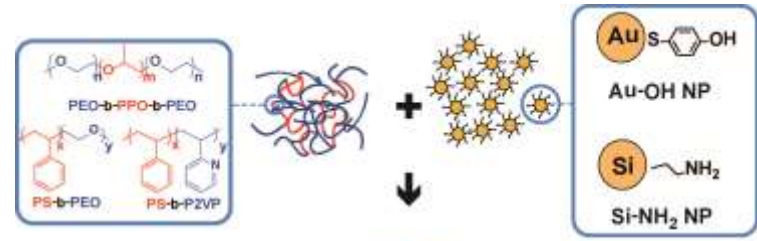
Linear Di-Block Copolymer Assembly



Increasing f



Additive-Driven Assembly of Hybrids



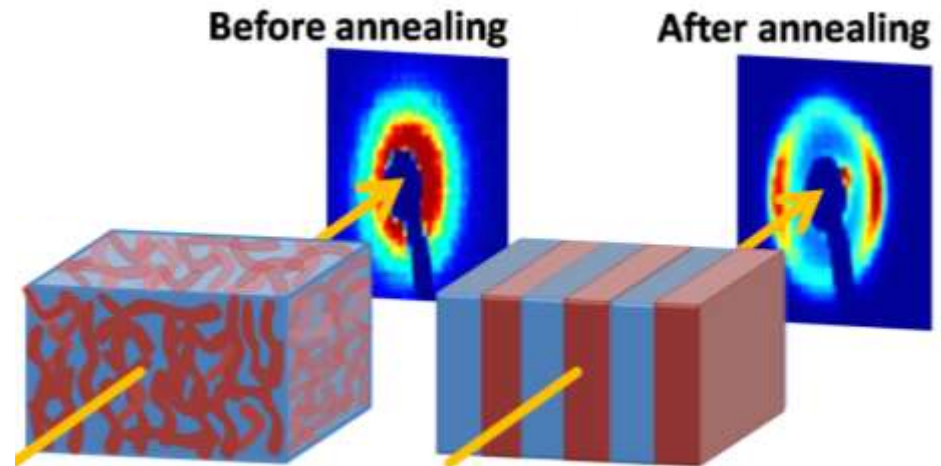
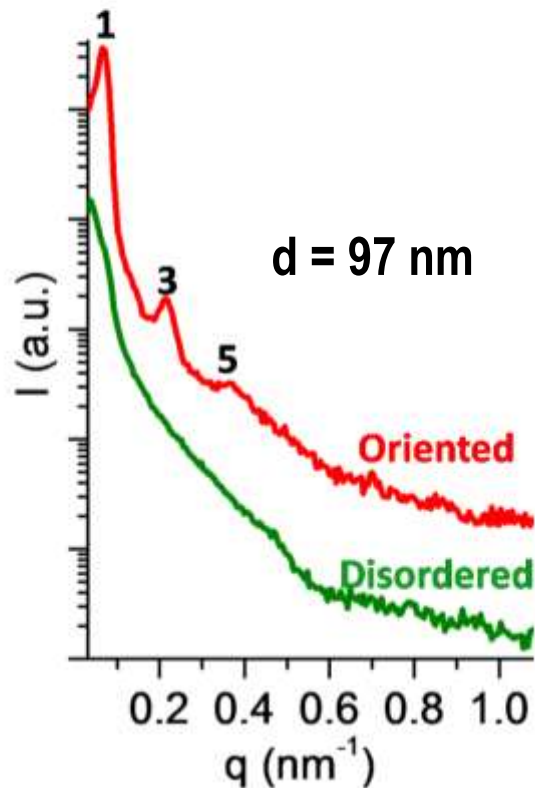
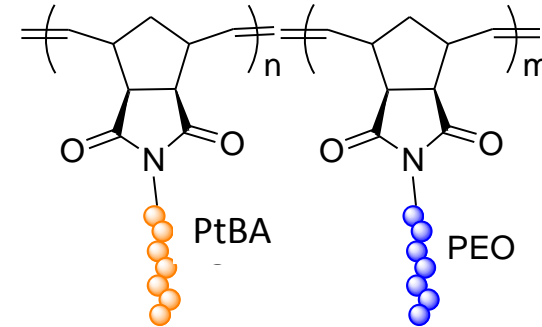
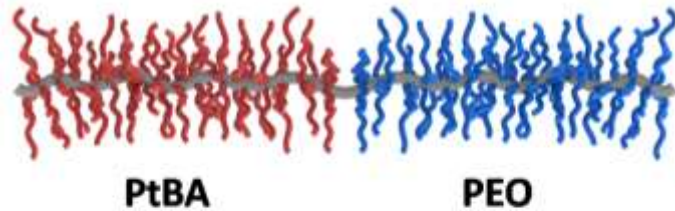
Some Additional Questions Regarding Block Copolymer/NP Co-Assembly for Practical Device Fabrication

- Can we tailor interactions to overcome entropic barriers to well ordered systems at high additive loadings?
- Can we achieve long range order in large volume elements?
- Can we direct the placement of two or more distinctive species of NPs to different domains of BCPs by introducing orthogonal intermolecular interactions?
- Can we create ordered systems containing “large” particles?
 - quantum dots, plasmonic Au
- Can we design the BCP template to be an active component or precursor to an active component within the device?
- Can we induce non-traditional but desirable morphologies?

(The answer to each of these questions is yes)

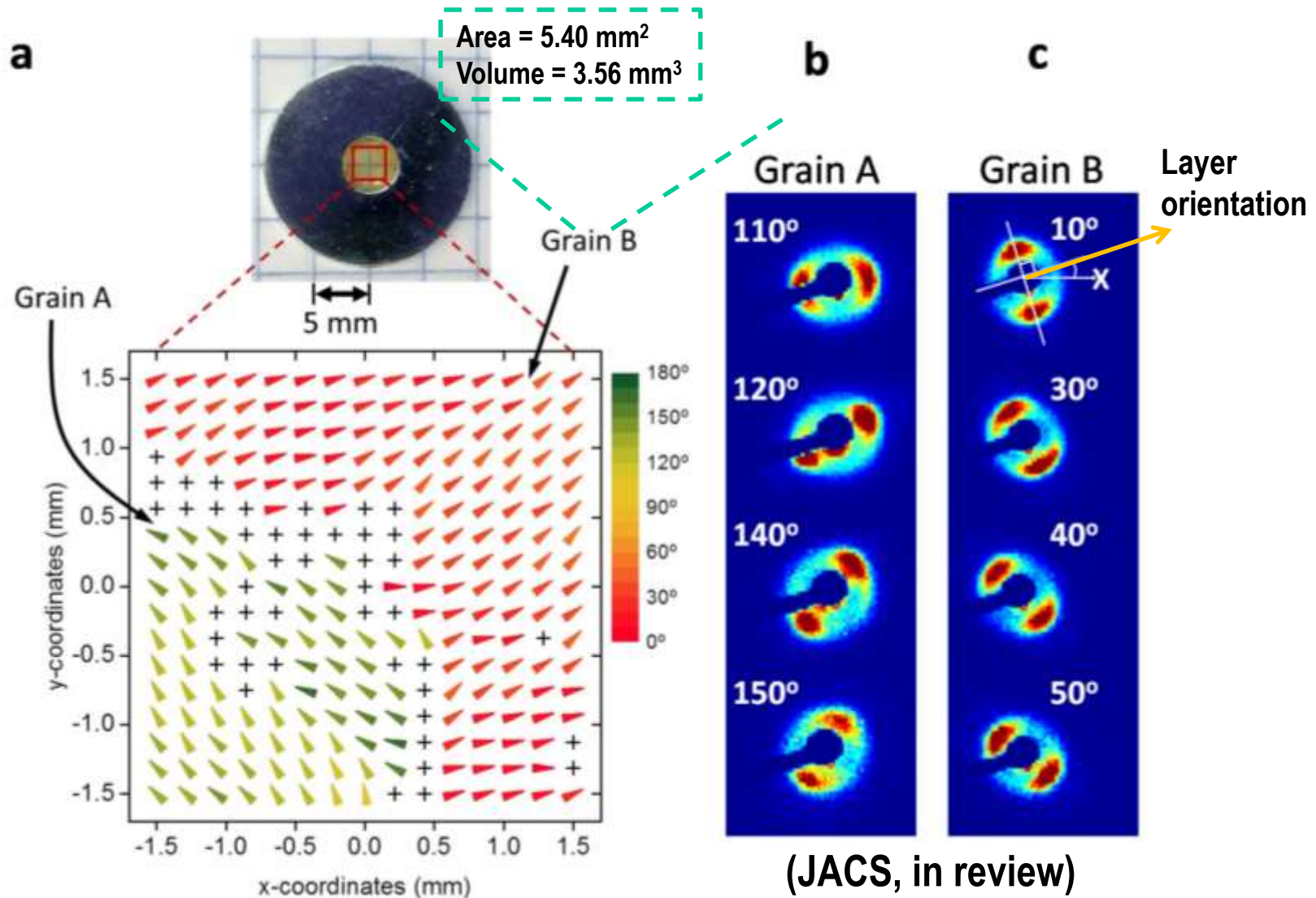
Block Copolymers for Optical Composites: Requires Large Domain Spacings and Large Volume Alignment

PtBA-PEO Brush Copolymers



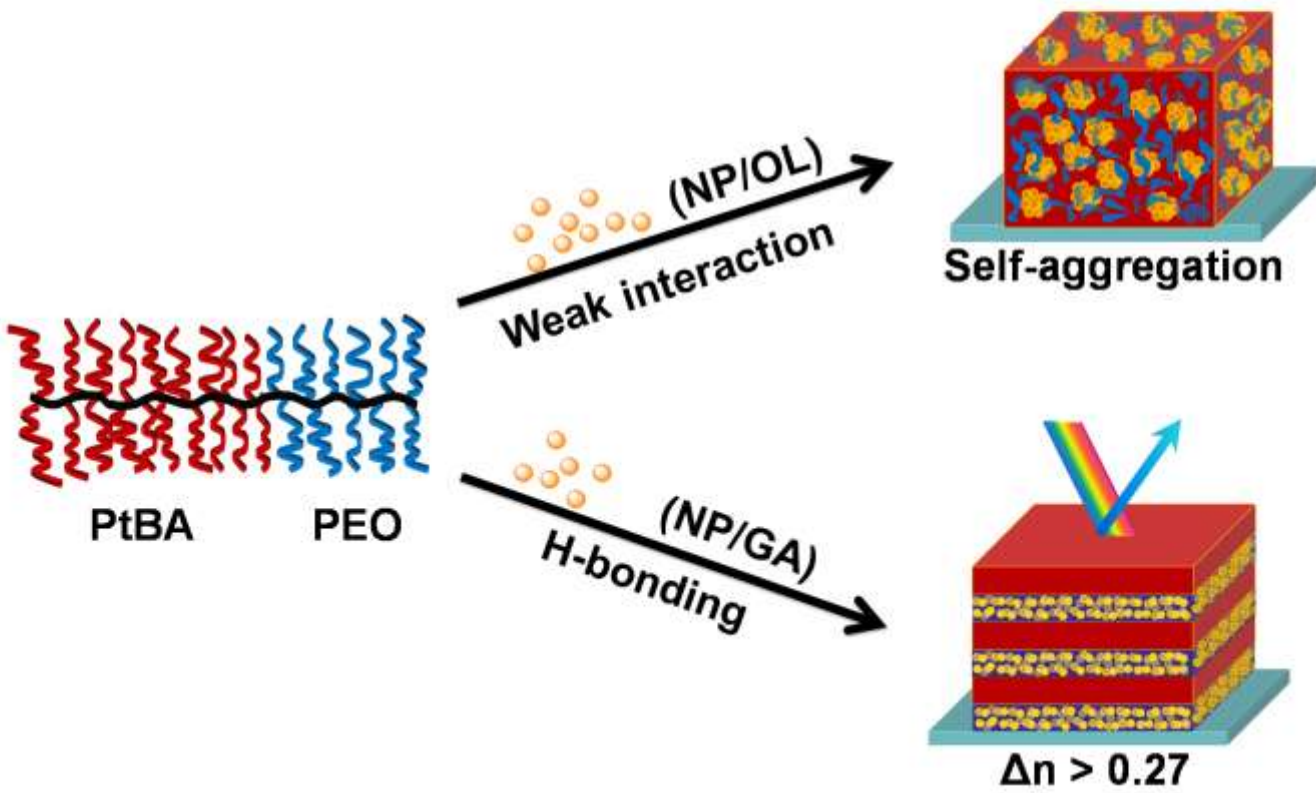
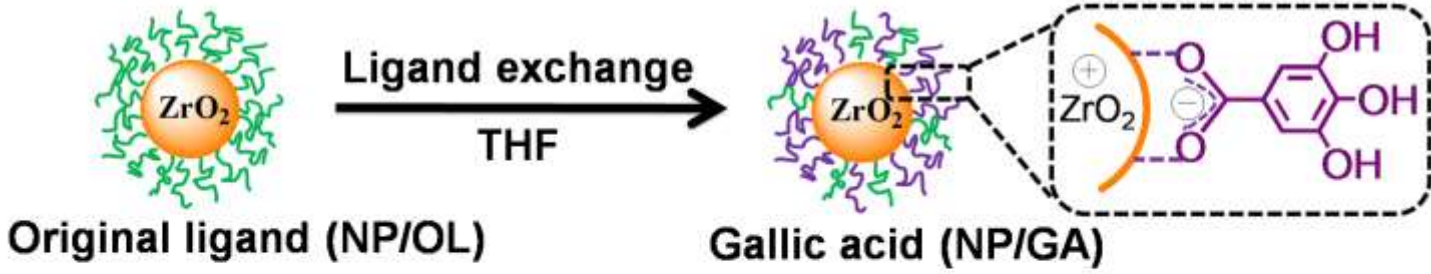
5 minutes at $110 \text{ }^{\circ}\text{C}$

Spontaneous Formation of Millimeter Scale Grains in PtBA-PEO Brush Copolymers

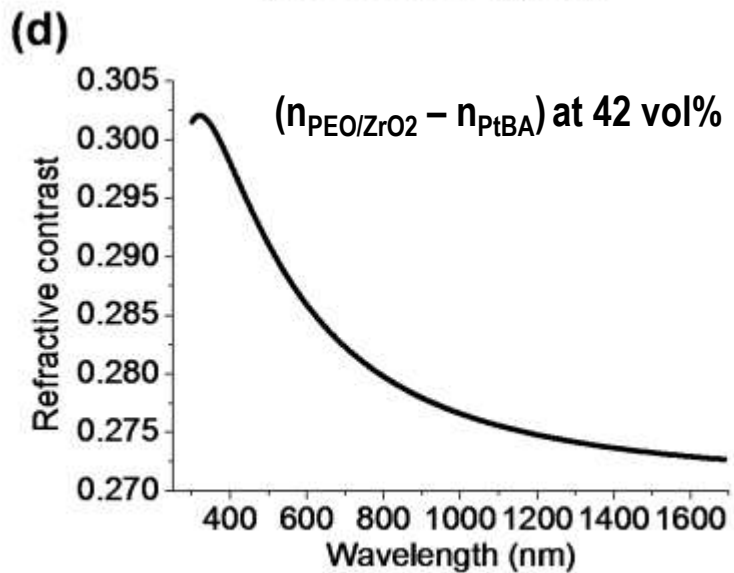
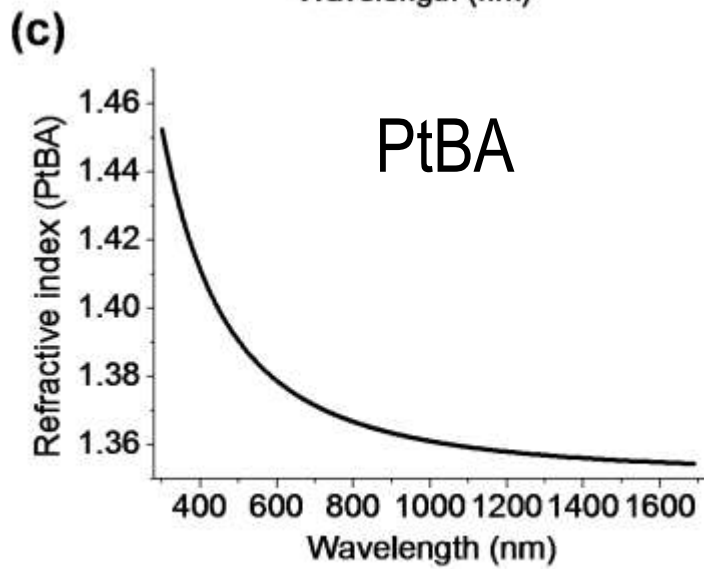
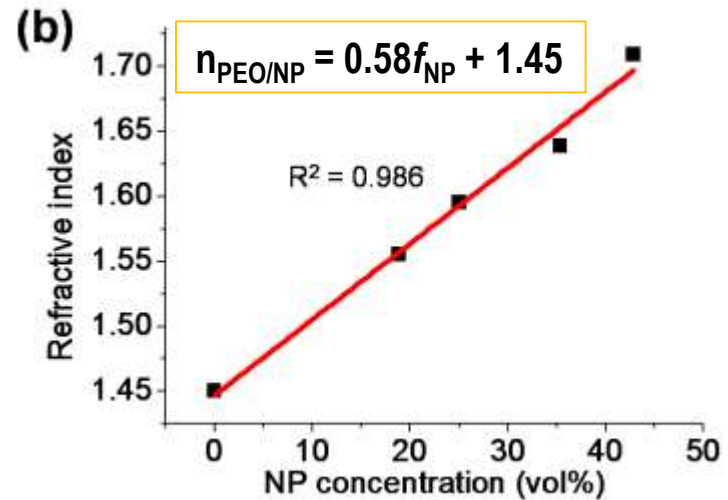
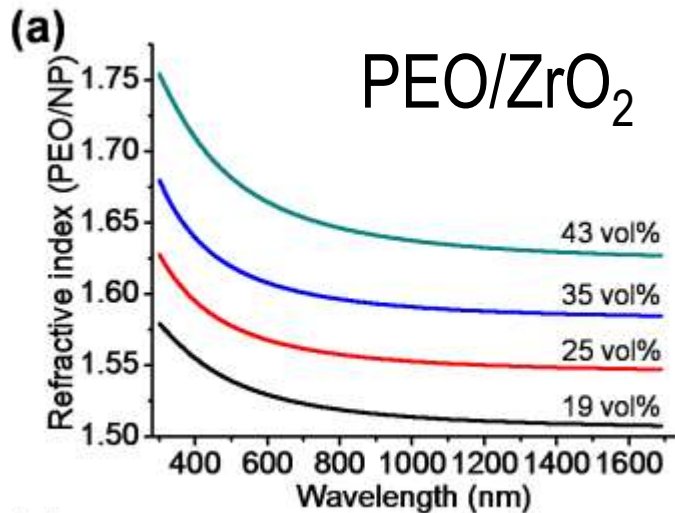


Mapping of the layer orientation in BBCP-A ($M_n = 1,850$ kg/mol, $f_{PEO} = 48.4\%$) using continuous SAXS scan measurements. The thickness of the sample is approximately 0.66 mm.

Self-assembled Photonic Hybrids with High Refractive Index Contrast

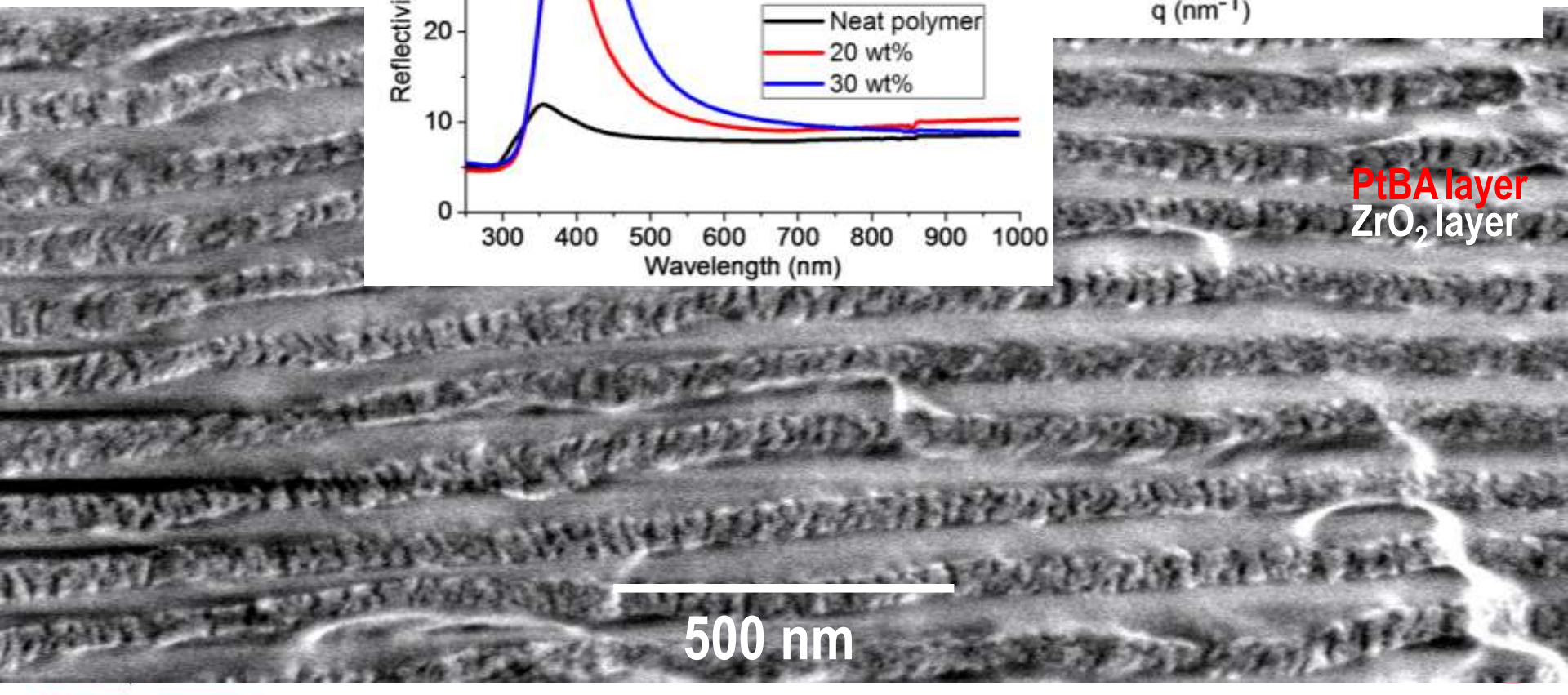
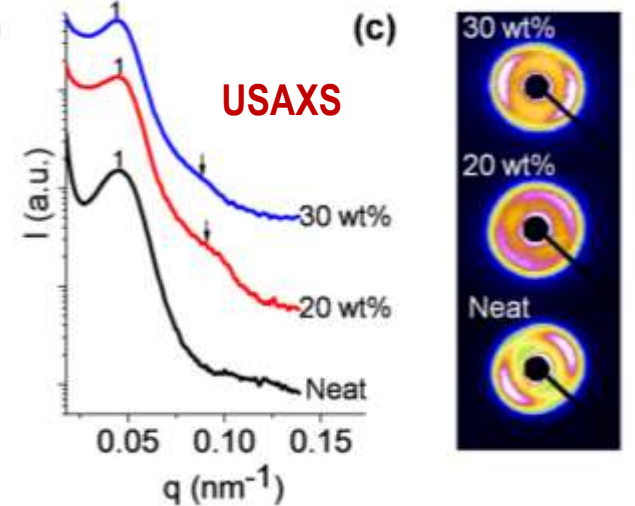
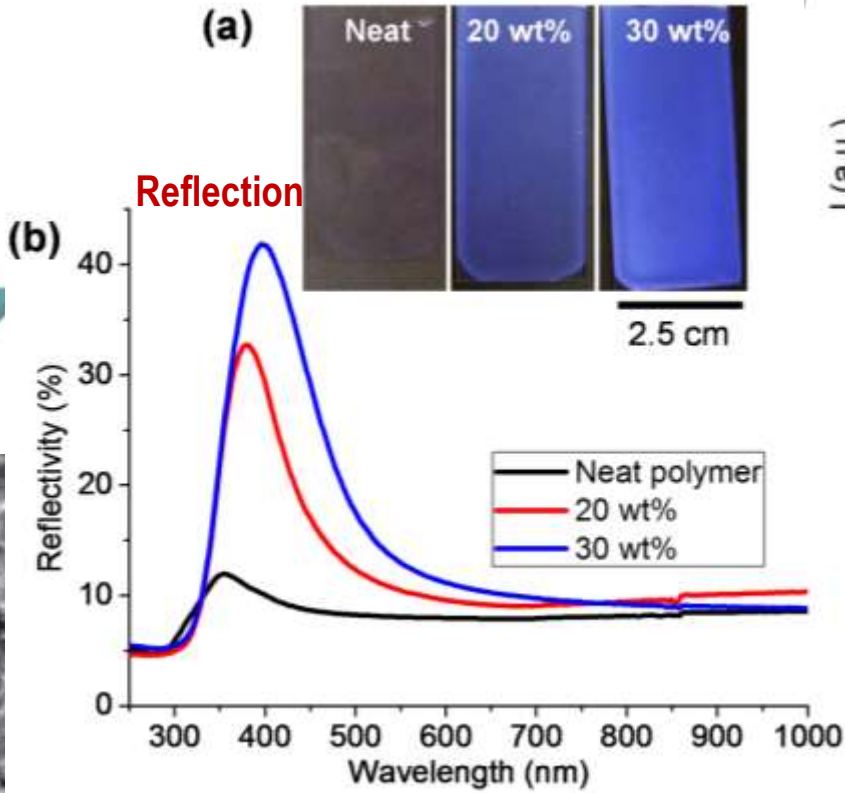
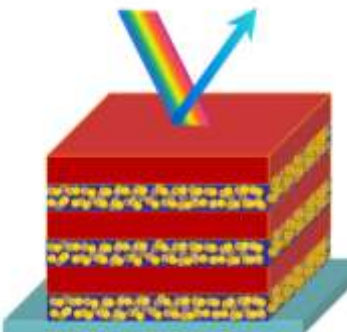


Refractive Indices of PEO/ZrO₂ Blends, PtBA, and RI Contrast

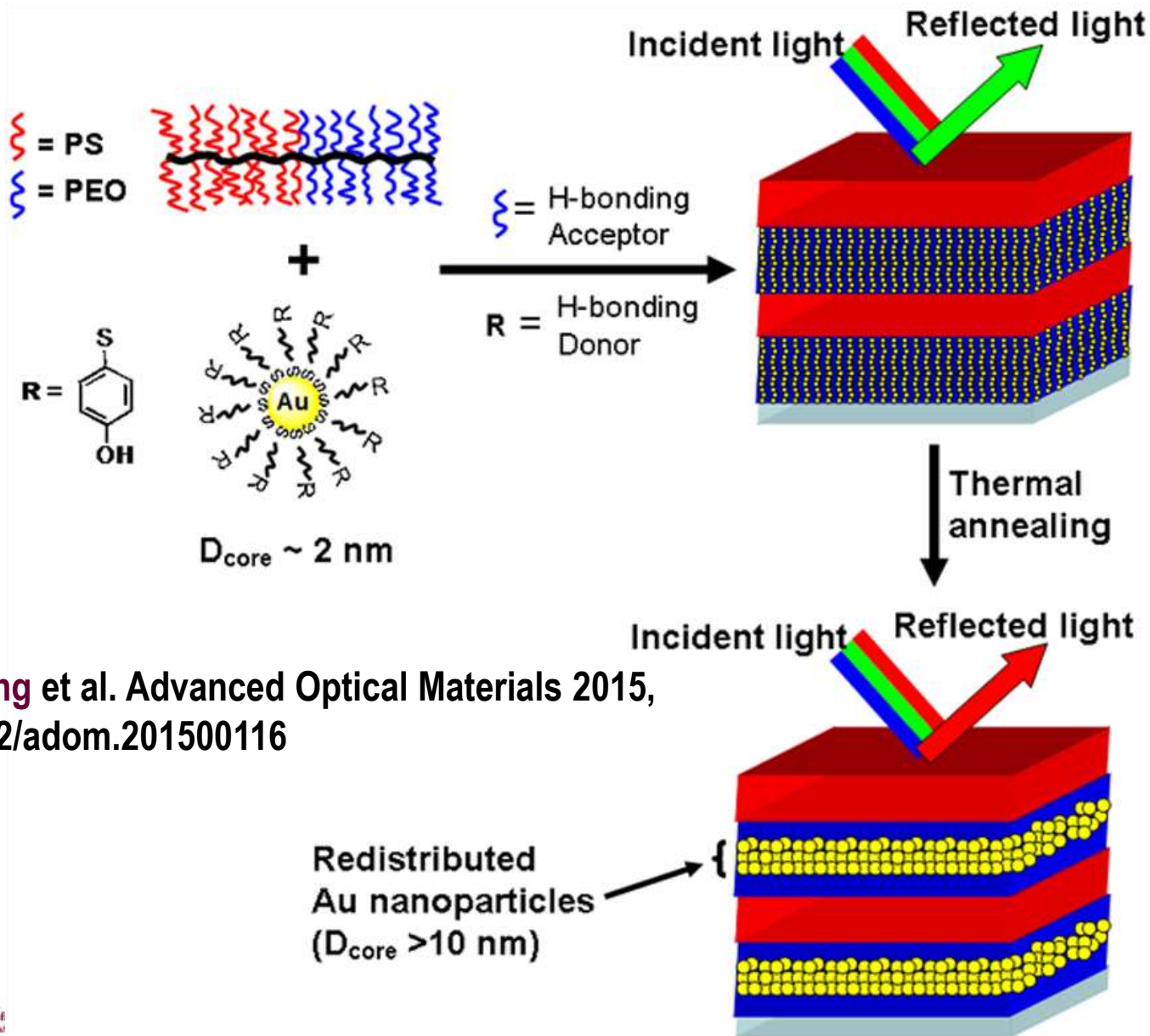


RI measured using variable angle spectroscopic ellipsometry (VASE)

Enhanced Reflection via Selective Incorporation of ZrO₂ within PEO Domains



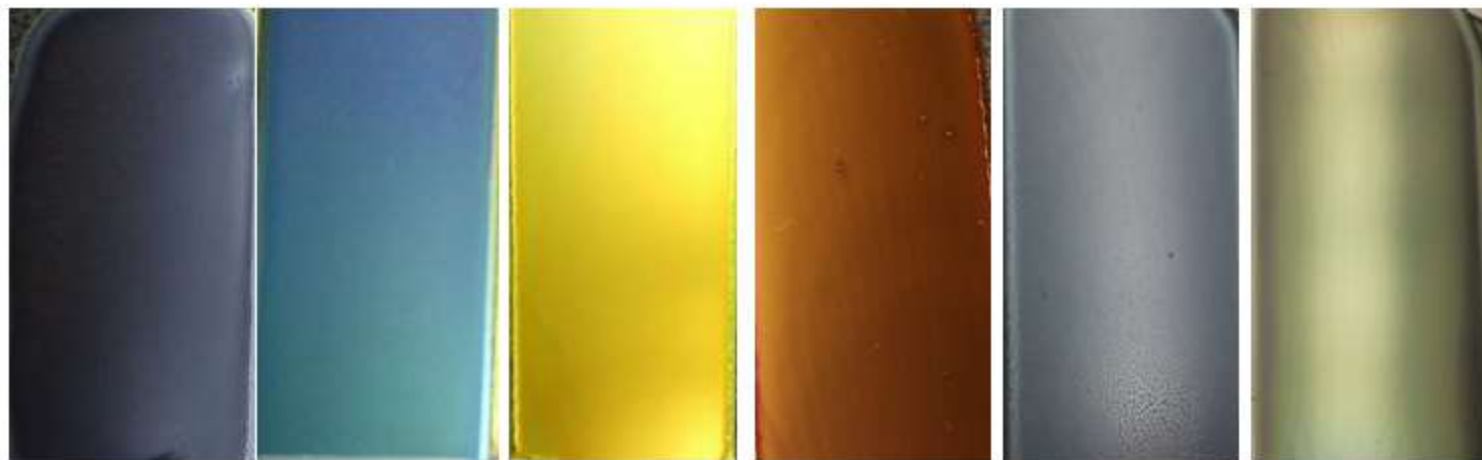
Tunable Metallodielectrics from Self-Assembly of Brush Block Copolymers and Gold Nanoparticles



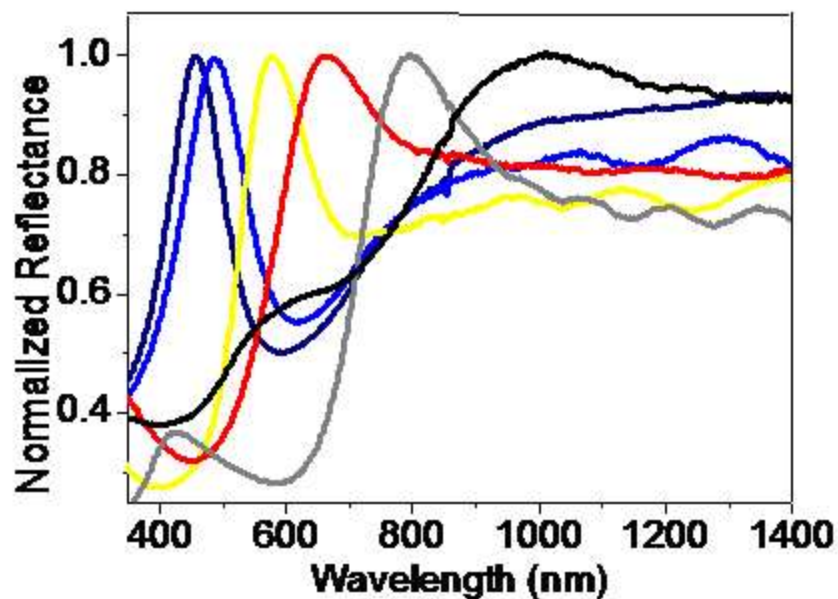
Dongpo Song et al. *Advanced Optical Materials* 2015,
DOI: 10.1002/adom.201500116

Tune-able Reflectance

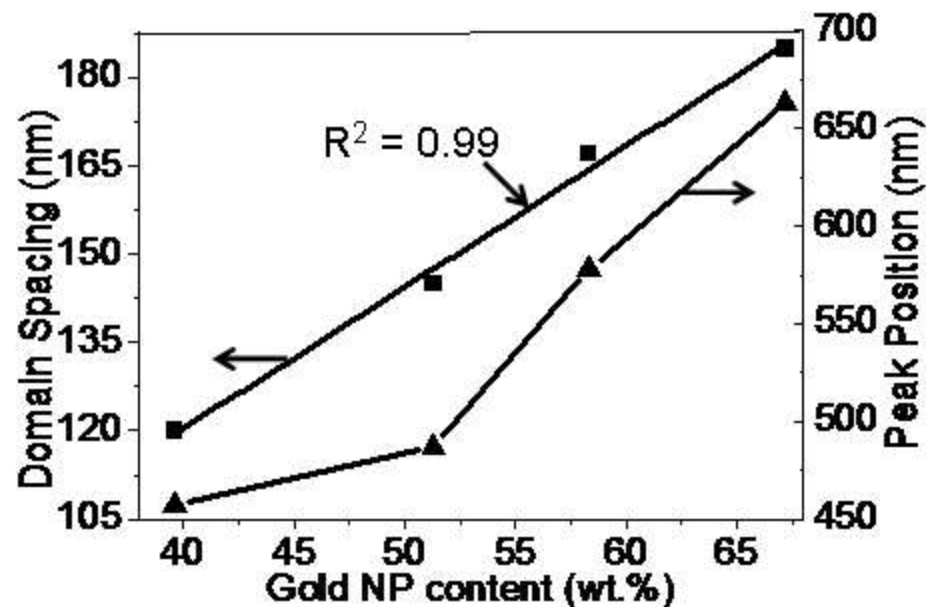
a



b

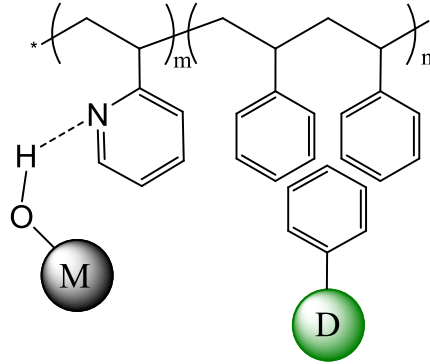
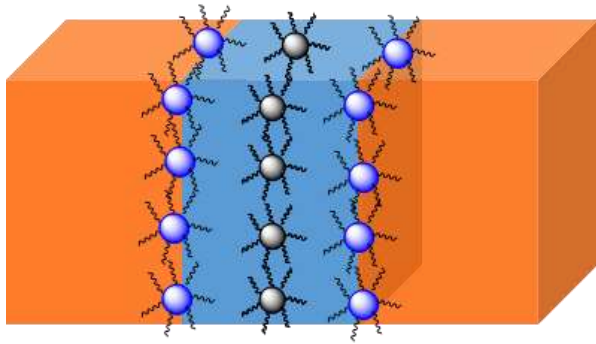


c

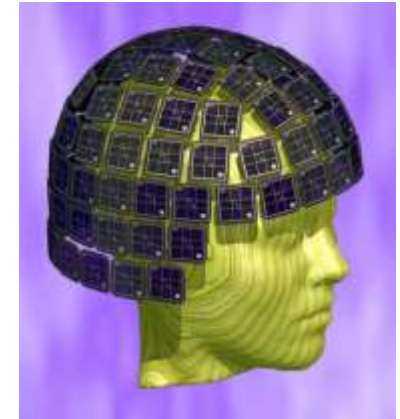
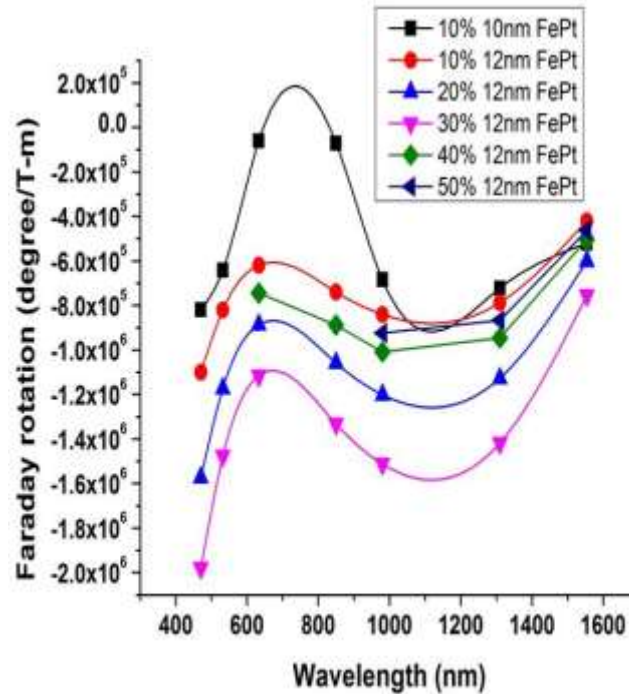
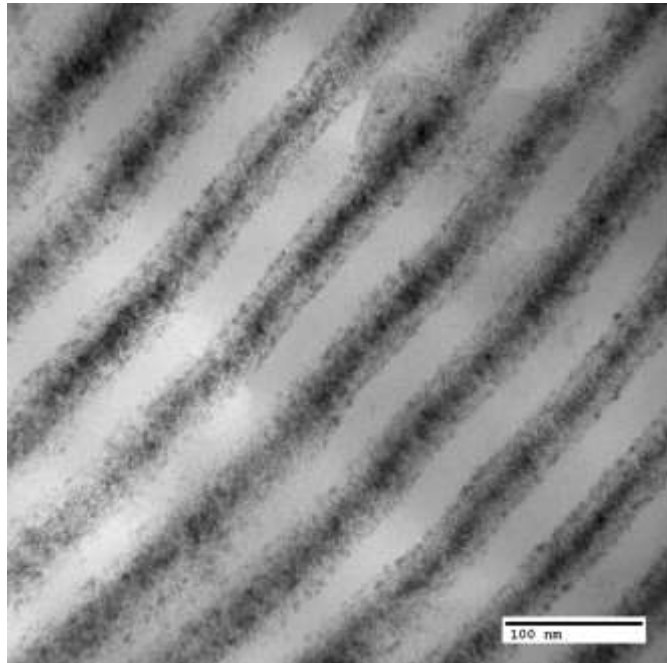
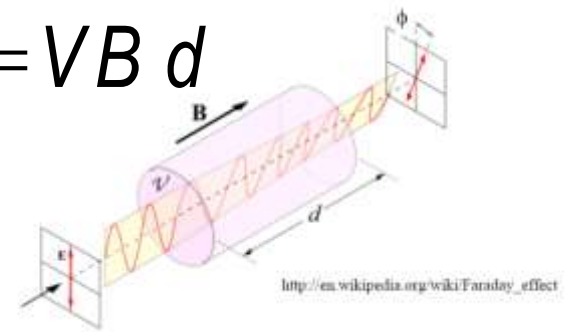


Magneto-Optic Metamaterials

PS-P2VP+FePt+ZrO₂+Additives

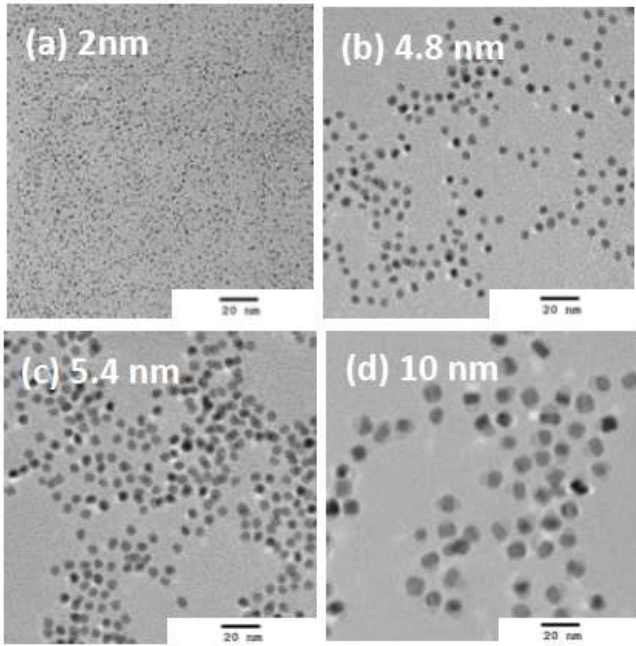


$$\theta = V B d$$

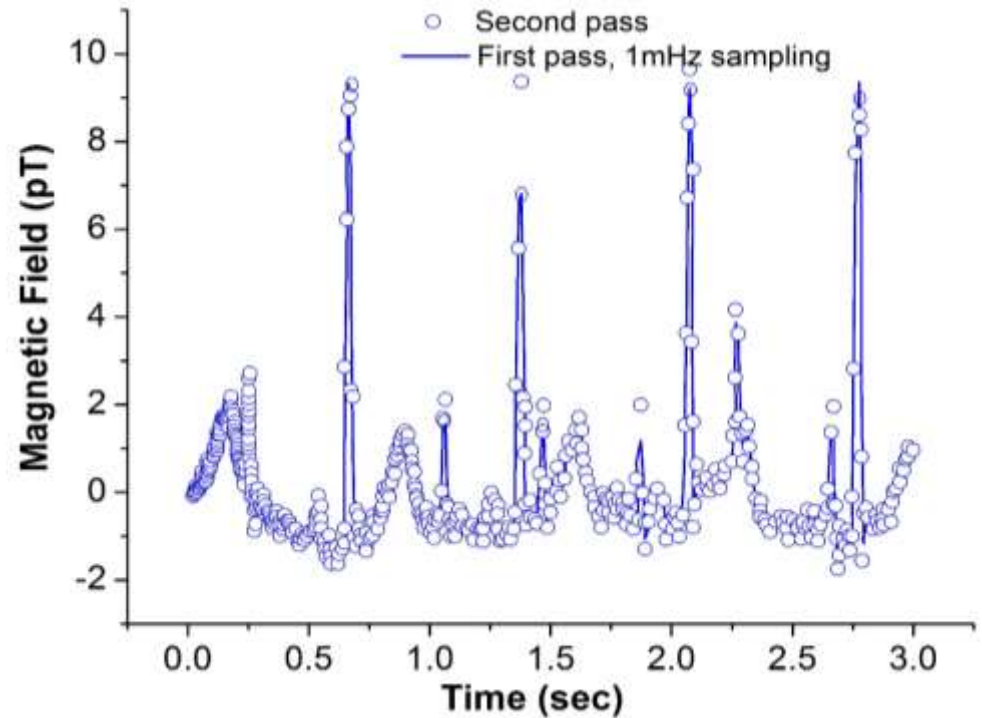




Magneto-optic composites for biological field imaging



FePt nanoparticles for magnetic field sensing



Sensing heartbeats with magneto-optic polymer nanocomposite based sensor

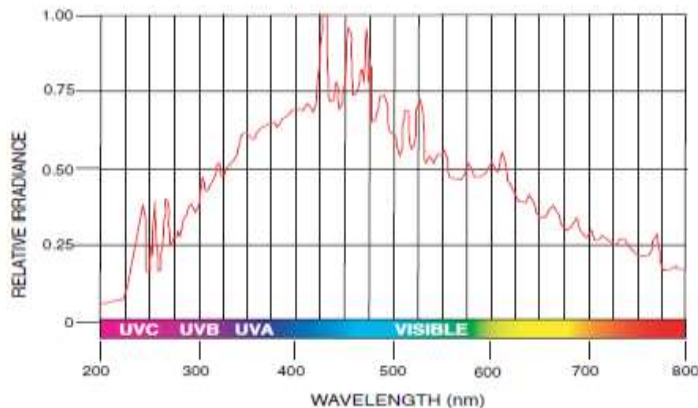
Ultrasensitive (femtotesla) magneto-optic sensors based on polymer nanoparticle composites have potential applications in heart and brain imaging among other areas



Scale for UMass Nanocoater



- Web Width: 6" Max, Coating Width: 5.75" Max
- Line Speed: 0.008-83 FPM/0.002-25.23 MPM
- Slot Die Coating Head: Thickness Range 2-600 um Wet
Solution Viscosity 10-4,000 Cps
Cored Die for Optional Heating to 95 Deg.C
- 2 Micro-Gravure Stations: Thickness Range 1-80 um Wet
Solution Viscosity 1-200 Cps
Coating Width 120mm/4.72"
- 2 Radiant Heat Dryers: Operating Limit 150 C
Positive Nitrogen Purging
4 Flowmeters Adjust Nitrogen
3 Thermocouples X-Web at both oven
entrances
and exits monitor Nitrogen temperature
- 2 In-line Ionizing Anti-static Bars
- 2 Ultrasonic Sensors/with Steering Rollers for Web Alignment

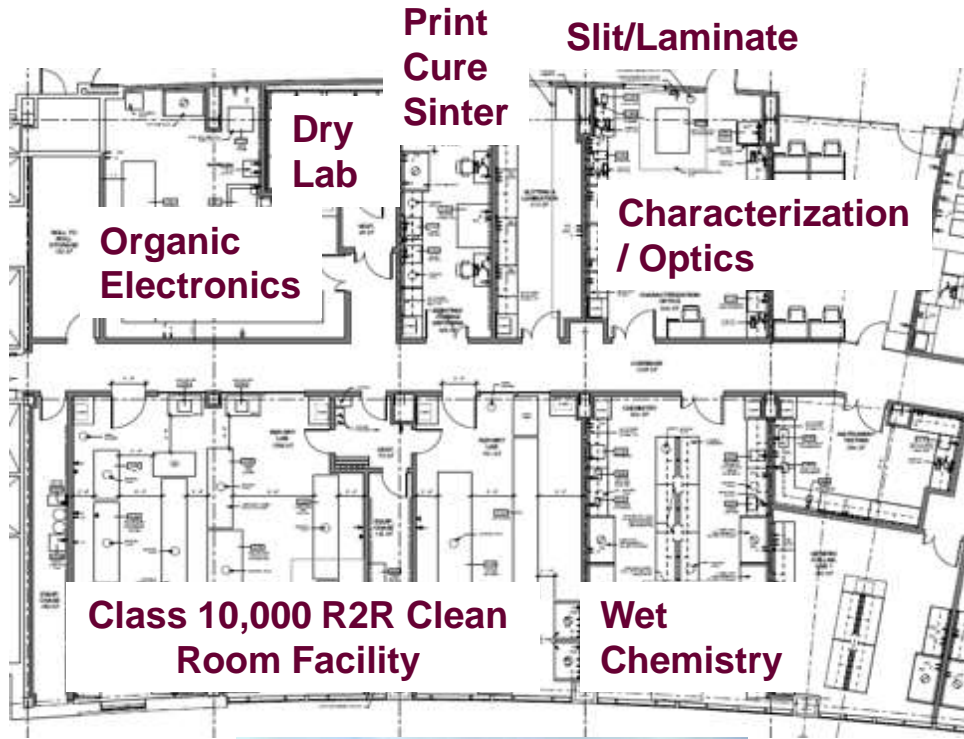


UV Cure Capability Added with the addition of the Xenon RC 847 LH 820 System.
Location allows for Pre-heating before the Cure station.
Pulse Energy & Rate: 13J/Pulse @ 100 pps
Lamp Optical Energy at 0.5" = 3.3 W/cm²

Spectrum of Xenon Pulsed Lamp

What is on the horizon?

APRM: Advanced Print and Roll-to-Roll Manufacturing Demonstration Facility Completion 2Q 2016



- R2R Sputter Deposition – 4 Target System (Choose - Cu, Au, Pd, ITO, Al₂O₃, SiO₂, Ni, Ti)
- R2R Deep Reactive Ion Etching / Ion Beam Milling (CF₄, O₂, SF₆, Ar, CHF₃, He)
- R2R Spatial ALD
- Advanced R2R Coater – Gravure and Slot Die with Controlled Emissions Exhaust
- R2R Inkjet Printing (Xaar) with Xenon Pulse Flash Lamp and NIR Cure (NovaCentrix)
- R2R Alignment Technology with overlay resolution of 1 micron
- Advanced R2R NIL with through master exposure and solvent assisted NIL
- R2R Optical Contact Lithography
- Sheet-Based and R2R Pick and Place
- Secondary processes: slitting/cutting, layer release/transfer, integration/bonding/assembly
- Dry Room
- Optomec Aerosol printing system
- Sheet-based Inkjet and Optical Cure
- Nanonex Batch NIL Tool NX-2608BA
- CHM legacy tools: UV-Assisted Nanoimprint and Nanocoater

<http://chm.pse.umass.edu/cphm/>

Watkins Research Group and CHM Staff



Takeaways

- Creation of intelligent devices by R2R is within reach
- R2R processing can reduce energy and resource demands
- Incorporation of self-assembly and additive-driven assembly enables new or advanced functionality, additive processing and lower cost
- R2R UV-Assisted NIL provides high-throughput access to device structures as small as 50 nm and on-roll device patterning
- Highly filled polymer/NP composites are useful active layers for devices and offer solution based alternatives to vacuum processing
- Direct patterning of crystalline metal oxide films on flexible substrates opens up options for printed inorganic devices with high integration densities
- Prototyping tools for R2R Hybrid Materials and R2R NIL accessible through CHM at UMass

